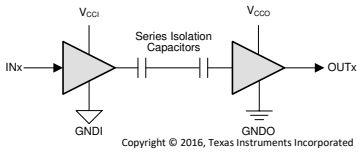
ISO676x 汎用 6 チャネル強化絶縁型デジタル・アイソレータ、堅牢な EMC

1 特長

- 50Mbps のデータ・レート
- 堅牢な絶縁バリア:
  - 1500V_{RMS} の動作電圧での長い寿命
  - 最高 5000V_{RMS} の絶縁定格
  - 最高 10kV のサージ耐量
  - CMTI:±150kV/µs (標準値)
- 広い電源電圧範囲:1.71V～1.89V、2.25V～5.5V
- 1.71V から 5.5V への電圧変換
- デフォルト出力 High (ISO676x) と Low (ISO676xF) を選択可能
- 広い温度範囲:-40℃～125℃
- チャネルごとに 1.6mA (標準値、1Mbps の場合)
- 小さい伝搬遅延時間:11ns (標準値)
- 堅牢な電磁気互換性 (EMC)
  - システム・レベルの ESD、EFT、サージ耐性
  - 低い放射
- Wide-SOIC (DW-16) パッケージ
- 安全関連の認証:
  - DIN EN IEC 60747-17 (VDE 0884-17)
  - UL 1577 部品認定プログラム
  - IEC 62368-1、IEC 61010-1、IEC 60601-1、GB 4943.1 認定

2 アプリケーション

- 電源
- 電力網、電力量計
- モータ・ドライブ
- ファクトリ・オートメーション
- ビル・オートメーション
- ライティング
- 家電製品



V_{CCI} = 入力電源、V_{CCO} = 出力電源
GNDI = 入力グランド、GNDO = 出力グランド

概略回路図

3 概要

ISO676x デバイスは、UL 1577 準拠の最大 5000V_{RMS} の絶縁定格を必要とするコスト重視のアプリケーションに理想的な高性能 6 チャネル・デジタル・アイソレータです。これらのデバイスは VDE、TUV、CSA、CQC の認定も受けています。

ISO676x デバイスは、CMOS または LVCMOS デジタル I/O を絶縁しながら、高い電磁気耐性と低い放射を低消費電力で実現します。各絶縁チャネルは、テキサス・インスツルメンツの二重容量性二酸化ケイ素 (SiO_2) 絶縁バリアで分離されたロジック入力および出力バッファを備えています。ISO676x デバイス・ファミリは、6 つのチャネルすべてが同じ方向、または 1、2、3 チャネルが逆方向で、他のチャネルが順方向など、可能なすべてのピン構成で利用可能です。入力電力または入力信号が失われた場合のデフォルト出力は、接尾辞 F のないデバイスでは HIGH、接尾辞 F のあるデバイスでは LOW です。詳細は「デバイスの機能モード」のセクションを参照してください。

これらのデバイスを絶縁電源と組み合わせて使用することで、UART、SPI、RS-485、RS-232、CAN などのデータ・バスのノイズ電流によって敏感な回路が損傷を受けることを防止できます。革新的なチップ設計およびレイアウト技法により、ISO676x は電磁両立性が大幅に強化されているため、システム・レベルの ESD、EFT、サージ、および放射のコンプライアンスを容易に達成できます。ISO676x デバイス・ファミリは、16 ピン SOIC ワイド・ボディ (DW) パッケージで供給される、旧世代品に対するピン・ツー・ピン・アップグレード製品です。

製品概要

部品番号 (1)	パッケージ	本体サイズ
ISO6760、ISO6765、ISO6761、ISO6761F、ISO6762、ISO6762F、ISO6763、ISO6763F	SOIC (DW)	10.30mm × 7.50mm

(1) 利用可能なパッケージについては、このデータシートの末尾にある注文情報を参照してください。

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4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision D (May 2022) to Revision E (January 2023) **Page**

- ドキュメント全体を通して標準名を「DIN V VDE V 0884-11:2017-01」から「DIN EN IEC 60747-17 (VDE 0884-17)」に変更 ... 1
- ドキュメント全体を通して、IEC/EN/CSA 60950-1 規格への参照を削除 ... 1
- ドキュメント全体を通して「計画中」とマークされた標準を更新し、認証番号を記載 ... 1
- ドキュメント全体を通して、すべての標準名から標準リビジョンおよび年への参照を削除 ... 1
- Added Maximum impulse voltage (V_{IMP}) specification per DIN EN IEC 60747-17 (VDE 0884-17) ... 10
- Changed test conditions and values of Maximum surge isolation voltage (V_{IOSM}) specification per DIN EN IEC 60747-17 (VDE 0884-17) ... 10
- Clarified method b test conditions of Apparent charge (q_{PD}) ... 10
- Changed Maximum surge isolation voltage (V_{IOSM}) from 6250 V_{PK} to 10000 V_{PK} ... 12
- Changed working voltage lifetime margin from: 87.5% to: 50%, minimum required insulation lifetime from: 37.5 years to: 30 years and insulation lifetime per TDDB from: 220 years to: 36 years in per DIN EN IEC 60747-17 (VDE 0884-17) ... 35
- Changed 図 9-8 per DIN EN IEC 60747-17 (VDE 0884-17) ... 35
- Updated to DW0016B mechanical drawing ... 39

Changes from Revision C (November 2021) to Revision D (May 2022) **Page**

- Updated CMTI spec for 5-V, 3.3-V and 2.5-V supply conditions ... 7

Changes from Revision B (November 2021) to Revision C (November 2021) **Page**

- Switched the labels for V_{CC1} falling and V_{CC2} rising in the graph legend of *Power Supply Undervoltage Threshold vs Free-Air Temperature* 26

Changes from Revision A (September 2021) to Revision B (November 2021) **Page**

- データシートに ISO6760、ISO6761、ISO6762 を追加..... 1

Changes from Revision * (August 2021) to Revision A (November 2021) **Page**

- デバイスのステータスを「量産データ」に更新..... 1

5 Pin Configuration and Functions

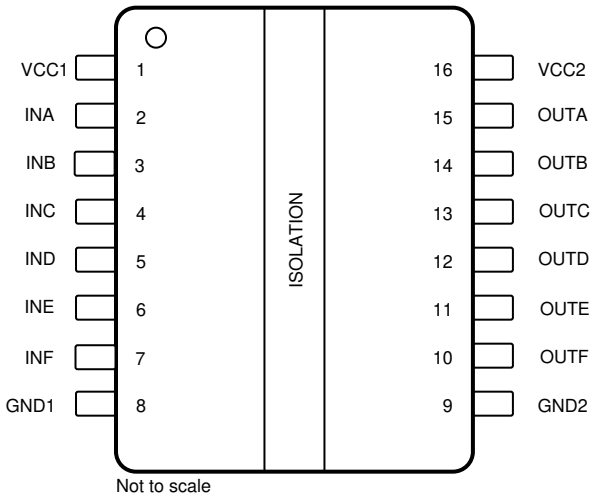


図 5-1. ISO6760 DW Package 16-Pin SOIC-WB Top View

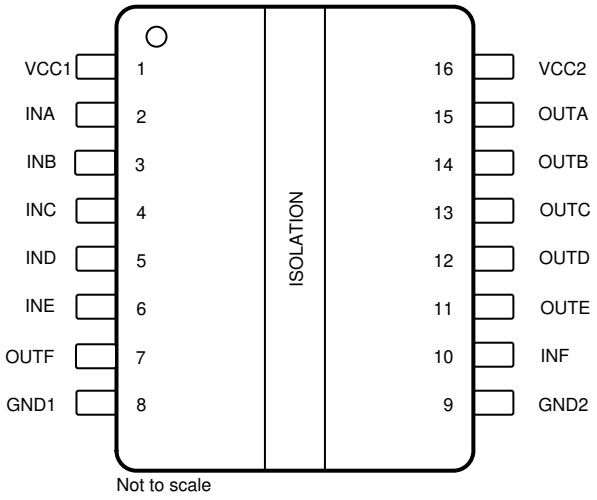


図 5-2. ISO6761 DW Package 16-Pin SOIC-WB Top View

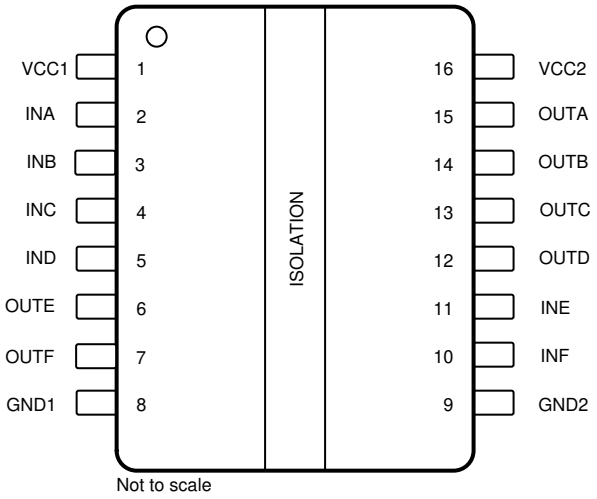


図 5-3. ISO6762 DW Package 16-Pin SOIC-WB Top View

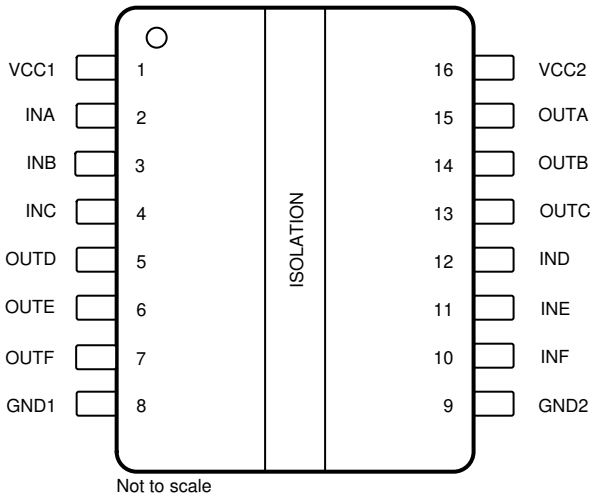


図 5-4. ISO6763 DW Package 16-Pin SOIC-WB Top View

表 5-1. Pin Functions

PIN					I/O	DESCRIPTION
NAME	NO.					
	ISO6760	ISO6761	ISO6762	ISO6763		
GND1	8	8	8	8	—	Ground connection for V_{CC1}
GND2	9	9	9	9	—	Ground connection for V_{CC2}
INA	2	2	2	2	I	Input, channel A
INB	3	3	3	3	I	Input, channel B
INC	4	4	4	4	I	Input, channel C
IND	5	5	5	12	I	Input, channel D
INE	6	6	11	11	I	Input, channel E
INF	7	10	10	10	I	Input, channel F
OUTA	15	15	15	15	O	Output, channel A
OUTB	14	14	14	14	O	Output, channel B
OUTC	13	13	13	13	O	Output, channel C
OUTD	12	12	12	5	O	Output, channel D

表 5-1. Pin Functions (continued)

PIN					I/O	DESCRIPTION
NAME	NO.					
	ISO6760	ISO6761	ISO6762	ISO6763		
OUTE	11	11	6	6	O	Output, channel E
OUTF	10	7	7	7	O	Output, channel F
V_{CC1}	1	1	1	1	—	Power supply, side 1
V_{CC2}	16	16	16	16	—	Power supply, side 2

6 Specifications

6.1 Absolute Maximum Ratings

See(1)

		MIN	MAX	UNIT
Supply Voltage (2)	V_{CC1} to GND1	-0.5	6	V
	V_{CC2} to GND2	-0.5	6	
Input/Output Voltage	INx to GNDx	-0.5	V_{CCX} + 0.5 (3)	V
	OUTx to GNDx	-0.5	V_{CCX} + 0.5 (3)	
Output Current	Io	-15	15	mA
Temperature	Operating junction temperature, T_J		150	°C
	Storage temperature, T_{stg}	-65	150	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values except differential I/O bus voltages are with respect to the local ground terminal (GND1 or GND2) and are peak voltage values
(3) Maximum voltage must not exceed 6 V.

6.2 ESD Ratings

(1) (2)

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1)	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(2)	±1500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V_{CC1} (1)	Supply Voltage Side 1 ((3))		1.71		1.89	V
V_{CC1} (1)	Supply Voltage Side 1 ((3))		2.25		5.5	V
V_{CC2} (1)	Supply Voltage Side 2 ((3))		1.71		1.89	V
V_{CC2} (1)	Supply Voltage Side 2 ((3))		2.25		5.5	V
Vcc (UVLO+)	UVLO threshold when supply voltage is rising			1.53	1.71	V
Vcc (UVLO-)	UVLO threshold when supply voltage is falling		1.1	1.41		V
Vhys (UVLO)	Supply voltage UVLO hysteresis		0.08	0.13		V
V_{IH}	High level Input voltage		0.7 x V_{CCI} (2)		V_{CCI}	V
V_{IL}	Low level Input voltage		0		0.3 x V_{CCI}	V
I_{OH}	High level output current	V_{CCO} (2) = 5 V	-4			mA
		V_{CCO} = 3.3 V	-2			mA
		V_{CCO} = 2.5 V	-1			mA
		V_{CCO} = 1.8 V	-1			mA
I_{OL}	Low level output current	V_{CCO} = 5 V			4	mA
		V_{CCO} = 3.3 V			2	mA
		V_{CCO} = 2.5 V			1	mA
		V_{CCO} = 1.8 V			1	mA
DR	Data Rate		0		50	Mbps
T_A	Ambient temperature		-40	25	125	°C

(1) V_{CC1} and V_{CC2} can be set independent of one another
(2) V_{CCI} = Input-side V_{CC}; V_{CCO} = Output-side V_{CC}
(3) The channel outputs are in undetermined state when 1.89 V < V_{CC1}, V_{CC2} < 2.25 V and 1.05 V < V_{CC1}, V_{CC2} < 1.71 V

6.4 Thermal Information

THERMAL METRIC (1)		ISO676x DW (SOIC) 16 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	68.8	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	31.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	32.7	°C/W
ψ_{JT}	Junction-to-top characterization parameter	13.5	°C/W
ψ_{JB}	Junction-to-board characterization parameter	32.1	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	n/a	°C/W

6.5 Power Ratings

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
ISO6760						
P_D	Maximum power dissipation (both sides)	$V_{CC1} = V_{CC2} = 5.5$ V, $T_J = 150°C$, $C_L = 15$ pF, Input a 25-MHz 50% duty cycle square wave			192	mW
P_{D1}	Maximum power dissipation (side-1)				45	mW
P_{D2}	Maximum power dissipation (side-2)				147	mW
ISO6761						
P_D	Maximum power dissipation (both sides)	$V_{CC1} = V_{CC2} = 5.5$ V, $T_J = 150°C$, $C_L = 15$ pF, Input a 25-MHz 50% duty cycle square wave			197	mW
P_{D1}	Maximum power dissipation (side-1)				63	mW
P_{D2}	Maximum power dissipation (side-2)				134	mW
ISO6762						
P_D	Maximum power dissipation (both sides)	$V_{CC1} = V_{CC2} = 5.5$ V, $T_J = 150°C$, $C_L = 15$ pF, Input a 25-MHz 50% duty cycle square wave			197	mW
P_{D1}	Maximum power dissipation (side-1)				81	mW
P_{D2}	Maximum power dissipation (side-2)				116	mW
ISO6763						
P_D	Maximum power dissipation (both sides)	$V_{CC1} = V_{CC2} = 5.5$ V, $T_J = 150°C$, $C_L = 15$ pF, Input a 25-MHz 50% duty cycle square wave			196	mW
P_{D1}	Maximum power dissipation (side-1)				98	mW
P_{D2}	Maximum power dissipation (side-2)				98	mW

6.6 Insulation Specifications

PARAMETER		TEST CONDITIONS	VALUE	UNIT
			DW-16	
CLR	External clearance(1)	Shortest terminal-to-terminal distance through air	>8	mm
CPG	External creepage(1)	Shortest terminal-to-terminal distance across the package surface	>8	mm
DTI	Distance through the insulation	Minimum internal gap (internal clearance)	>17	um
CTI	Comparative tracking index	DIN EN 60112 (VDE 0303-11); IEC 60112	>600	V
	Material group	According to IEC 60664-1	I	
	Overvoltage category per IEC 60664-1	Rated mains voltage ≤ 600 V_{RMS}	I-IV	
		Rated mains voltage ≤ 1000 V_{RMS}	I-III	
DIN EN IEC 60747-17 (VDE 0884-17)((2))				
V_{IORM}	Maximum repetitive peak isolation voltage	AC voltage (bipolar)	2121	V_{PK}
V_{IOWM}	Maximum working isolation voltage	AC voltage; Time dependent dielectric breakdown (TDDB) Test; See 図 9-8	1500	V_{RMS}
		DC voltage	2121	V_{DC}
V_{IOTM}	Maximum transient isolation voltage	$V_{TEST} = V_{IOTM}$, t = 60 s (qualification); $V_{TEST} = 1.2 \times V_{IOTM}$, t= 1 s (100% production)	7071	V_{PK}
V_{IMP}	Maximum impulse voltage((3))	Tested in air, 1.2/50-us waveform per IEC 62368-1	7692	V_{PK}
V_{IOSM}	Maximum surge isolation voltage((4))	$V_{IOSM} \geq 1.3 \times V_{IMP}$; Tested in oil (qualification test), 1.2/50-µs waveform per IEC 62368-1	10000	V_{PK}
q_{pd}	Apparent charge(5)	Method a, After Input-output safety test subgroup 2/3, $V_{ini} = V_{IOTM}$, t_{ini} = 60 s; $V_{pd(m)} = 1.2 \times V_{IORM}$, t_m = 10 s	≤5	pC
		Method a, After environmental tests subgroup 1, $V_{ini} = V_{IOTM}$, t_{ini} = 60 s; $V_{pd(m)} = 1.6 \times V_{IORM}$, t_m = 10 s	≤5	
		Method b: At routine test (100% production) and preconditioning (type test); $V_{ini} = 1.2 \times V_{IOTM}$, t_{ini} = 1 s; $V_{pd(m)} = 1.875 \times V_{IORM}$, t_m = 1 s (method b1) or $V_{pd(m)} = V_{ini}$, $t_m = t_{ini}$ (method b2)	≤5	
C_{IO}	Barrier capacitance, input to output(6)	V_{IO} = 0.4 x sin (2πft), f = 1 MHz	~1	pF
R_{IO}	Isolation resistance(6)	V_{IO} = 500 V, T_A = 25°C	$>10^{12}$	Ω
		V_{IO} = 500 V, 100°C ≤ T_A ≤ 125°C	$>10^{11}$	
		V_{IO} = 500 V at T_S = 150°C	$>10^{9}$	
	Pollution degree		2	
	Climatic category		40/125/21	
UL 1577				
V_{ISO}	Maximum withstanding isolation voltage	$V_{TEST} = V_{ISO}$, t = 60 s (qualification), $V_{TEST} = 1.2 \times V_{ISO}$, t = 1 s (100% production)	5000	V_{RMS}

(1) Creepage and clearance requirements should be applied according to the specific equipment isolation standards of an application. Care should be taken to maintain the creepage and clearance distance of a board design to ensure that the mounting pads of the isolator on the printed-circuit board do not reduce this distance. Creepage and clearance on a printed-circuit board become equal in certain cases. Techniques such as inserting grooves and/or ribs on a printed-circuit board are used to help increase these specifications.
(2) This coupler is suitable for *safe electrical insulation* only within the safety ratings. Compliance with the safety ratings shall be ensured by means of suitable protective circuits.
(3) Testing is carried out in air to determine the surge immunity of the package.
(4) Testing is carried out in oil to determine the intrinsic surge immunity of the isolation barrier.
(5) Apparent charge is electrical discharge caused by a partial discharge (pd).

(6) All pins on each side of the barrier tied together creating a two-terminal device.

6.7 Safety-Related Certifications

VDE	CSA	UL	CQC	TUV
Certified according to DIN EN IEC 60747-17 (VDE 0884-17)	Certified according to IEC 62368-1, IEC 61010-1 and IEC 60601	Certified according to UL 1577 Component Recognition Program	Certified according to GB 4943.1	Certified according to EN 61010-1 and EN 62368-1
Maximum transient isolation voltage, 7071 V_{PK}; Maximum repetitive peak isolation voltage, 2121 V_{PK}; Maximum surge isolation voltage, 10000 V_{PK}	600 V_{RMS} reinforced insulation per CSA 62368-1 and IEC 62368-1; 600 V_{RMS} reinforced insulation per CSA 61010-1 and IEC 61010-1 (pollution degree 2, material group I); 2 MOPP (Means of Patient Protection) per CSA 60601-1 and IEC 60601-1, 250 V_{RMS} max working voltage	Single protection, 5000 V_{RMS}	Reinforced insulation, Altitude ≤ 5000 m, Tropical Climate, 700 V_{RMS} maximum working voltage	5000 V_{RMS} reinforced insulation per EN 61010-1 and EN 62368-1 up to working voltage of 600 V_{RMS}
Certificate number: 40040142	Master contract number: 220991	File number: E181974	Certificate number: CQC21001304083	Client ID number: 077311

6.8 Safety Limiting Values

Safety limiting(1) intends to minimize potential damage to the isolation barrier upon failure of input or output circuitry.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DW-16 PACKAGE						
I_S	Safety input, output, or supply current (1)	$R_{\theta JA}$ =68.8°C/W, V_I = 5.5 V, T_J = 150°C, T_A = 25°C			330	mA
		$R_{\theta JA}$ = 68.8°C/W, V_I = 3.6 V, T_J = 150°C, T_A = 25°C			504	mA
		$R_{\theta JA}$ = 68.8°C/W, V_I = 2.75 V, T_J = 150°C, T_A = 25°C			660	mA
		$R_{\theta JA}$ = 68.8°C/W, V_I = 1.89 V, T_J = 150°C, T_A = 25°C			956	mA
P_S	Safety input, output, or total power (1)	$R_{\theta JA}$ = 68.8°C/W, T_J = 150°C, T_A = 25°C			1820	mW
T_S	Maximum safety temperature (1)				150	°C

(1) The maximum safety temperature, T_S, has the same value as the maximum junction temperature, T_J, specified for the device. The I_S and P_S parameters represent the safety current and safety power respectively. The maximum limits of I_S and P_S should not be exceeded. These limits vary with the ambient temperature, T_A.
The junction-to-air thermal resistance, $R_{\theta JA}$, in the table is that of a device installed on a high-K test board for leaded surface-mount packages. Use these equations to calculate the value for each parameter:
$T_J = T_A + R_{\theta JA} \times P$, where P is the power dissipated in the device.
$T_{J(max)} = T_S = T_A + R_{\theta JA} \times P_S$, where $T_{J(max)}$ is the maximum allowed junction temperature.
$P_S = I_S \times V_I$, where V_I is the maximum input voltage.

6.9 Electrical Characteristics—5-V Supply

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	I_{OH} = -4 mA; See 図 7-1	V_{CCO} - 0.4			V
V_{OL}	Low-level output voltage	I_{OL} = 4 mA; See 図 7-1			0.4	V
$V_{IT+(IN)}$	Rising input switching threshold				0.7 x V_{CCI} (1)	V
$V_{IT-(IN)}$	Falling input switching threshold		0.3 x V_{CCI}			V
$V_{I(HYS)}$	Input threshold voltage hysteresis		0.1 x V_{CCI}			V
I_{IH}	High-level input current	V_{IH} = V_{CCI} (1) at INx			10	µA
I_{IL}	Low-level input current	V_{IL} = 0 V at INx	-10			µA
CMTI	Common mode transient immunity	V_I = V_{CC} or 0 V, V_{CM} = 1200 V; See 図 7-3	100	150		kV/us
C_i	Input Capacitance (2)	V_I = V_{CC}/ 2 + 0.4×sin(2πft), f = 2 MHz, V_{CC} = 5 V		2.8		pF

(1) V_{CCI} = Input-side V_{CC}; V_{CCO} = Output-side V_{CC}
(2) Measured from input pin to same side ground.

6.10 Supply Current Characteristics—5-V Supply

V_{CC1} = V_{CC2} = 5 V ±10% (over recommended operating conditions unless otherwise noted).

PARAMETER	TEST CONDITIONS		SUPPLY CURRENT	MIN	TYP	MAX	UNIT
ISO6760							
Supply current - DC signal	VI = VCC1 (ISO6760); VI = 0 V (ISO6760 with F suffix)		I_{CC1}		2.2	2.8	mA
			I_{CC2}		3.1	5.2	
	VI = 0 V (ISO6760); VI = VCC1 (ISO6760 with F suffix)		I_{CC1}		8.3	11.1	
			I_{CC2}		3.4	5.7	
Supply current - AC signal	All channels switching with square wave clock input; CL = 15 pF	1 Mbps	I_{CC1}		5.3	7.0	
			I_{CC2}		3.7	5.9	
		10 Mbps	I_{CC1}		5.4	7.2	
			I_{CC2}		7.0	9.7	
		50 Mbps	I_{CC1}		6.3	8.1	
			I_{CC2}		21.9	26.6	
ISO6761							
Supply current - DC signal	VI = VCC1 (ISO6761); VI = 0 V (ISO6761 with F suffix)		I_{CC1}		2.4	3.5	mA
			I_{CC2}		3.6	5.8	
	VI = 0 V (ISO6761); VI = VCC1 (ISO6761 with F suffix)		I_{CC1}		7.6	10.4	
			I_{CC2}		5.0	7.6	
Supply current - AC signal	All channels switching with square wave clock input; CL = 15 pF	1 Mbps	I_{CC1}		5.1	7.0	
			I_{CC2}		4.6	7.0	
		10 Mbps	I_{CC1}		5.8	7.8	
			I_{CC2}		7.4	10.2	
		50 Mbps	I_{CC1}		8.9	11.4	
			I_{CC2}		20.0	24.4	
ISO6762							

V_{CC1} = V_{CC2} = 5 V ±10% (over recommended operating conditions unless otherwise noted).

PARAMETER	TEST CONDITIONS		SUPPLY CURRENT	MIN	TYP	MAX	UNIT
Supply current - DC signal	VI = VCC1 (ISO6762); VI = 0 V (ISO6762 with F suffix)		I_{CC1}		2.7	4.1	mA
			I_{CC2}		3.3	5.2	
	VI = 0 V (ISO6762); VI = VCC1 (ISO6762 with F suffix)		I_{CC1}		6.9	9.7	
			I_{CC2}		5.6	8.3	
Supply current - AC signal	All channels switching with square wave clock input; CL = 15 pF	1 Mbps	I_{CC1}		5	7	
			I_{CC2}		4.7	7	
		10 Mbps	I_{CC1}		6.2	8.4	
			I_{CC2}		7	9.6	
		50 Mbps	I_{CC1}		11.7	14.6	
			I_{CC2}		17.2	21.1	
ISO6763							
Supply current - DC signal	V_I = V_{CCI} (ISO6763); V_I = 0 V (ISO6763 with F suffix)		I_{CC1}, I_{CC2}		3	4.7	mA
	V_I = 0 V (ISO6763); V_I = V_{CCI} (ISO6763 with F suffix)		I_{CC1}, I_{CC2}		6.3	9	
Supply current - AC signal	All channels switching with square wave clock input; C_L = 15 pF	1 Mbps	I_{CC1}, I_{CC2}		4.8	7	
		10 Mbps	I_{CC1}, I_{CC2}		6.6	9	
		50 Mbps	I_{CC1}, I_{CC2}		14.4	17.8	

6.11 Electrical Characteristics—3.3-V Supply

V_{CC1} = V_{CC2} = 3.3 V ±10% (over recommended operating conditions unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	I_{OH} = -2mA ; See 図 7-1	V_{CCO} - 0.2			V
V_{OL}	Low-level output voltage	I_{OL} = 2mA ; See 図 7-1			0.2	V
$V_{IT+(IN)}$	Rising input switching threshold				0.7 x V_{CCI} (1)	V
$V_{IT-(IN)}$	Falling input switching threshold		0.3 x V_{CCI}			V
$V_{I(HYS)}$	Input threshold voltage hysteresis		0.1 x V_{CCI}			V
I_{IH}	High-level input current	V_{IH} = V_{CCI} (1) at INx			10	µA
I_{IL}	Low-level input current	V_{IL} = 0 V at INx	-10			µA
CMTI	Common mode transient immunity	V_I = V_{CC} or 0 V, V_{CM} = 1200 V; See 図 7-3	100	150		kV/us
C_i	Input Capacitance(2)	V_I = V_{CC}/ 2 + 0.4×sin(2πft), f = 2 MHz, V_{CC} = 3.3 V		2.8		pF

(1) V_{CCI} = Input-side V_{CC}; V_{CCO} = Output-side V_{CC}
(2) Measured from input pin to same side ground.

6.12 Supply Current Characteristics—3.3-V Supply

V_{CC1} = V_{CC2} = 3.3 V ±10% (over recommended operating conditions unless otherwise noted).

PARAMETER	TEST CONDITIONS		SUPPLY CURRENT	MIN	TYP	MAX	UNIT
ISO6760							
Supply current - DC signal	VI = VCC1 (ISO6760); VI = 0 V (ISO6760 with F suffix)		I_{CC1}		2.2	2.8	mA
			I_{CC2}		3.1	5.1	
	VI = 0 V (ISO6760); VI = VCC1 (ISO6760 with F suffix)		I_{CC1}		8.3	10.9	
			I_{CC2}		3.4	5.6	
Supply current - AC signal	All channels switching with square wave clock input; CL = 15 pF	1 Mbps	I_{CC1}		5.3	6.9	
			I_{CC2}		3.5	5.7	
		10 Mbps	I_{CC1}		5.3	7	
			I_{CC2}		5.9	8.5	
		50 Mbps	I_{CC1}		5.9	7.6	
			I_{CC2}		16.6	20.9	
ISO6761							
Supply current - DC signal	VI = VCC1 (ISO6761); VI = 0 V (ISO6761 with F suffix)		I_{CC1}		2.4	3.5	mA
			I_{CC2}		3.6	5.8	
	VI = 0 V (ISO6761); VI = VCC1 (ISO6761 with F suffix)		I_{CC1}		7.5	10.3	
			I_{CC2}		4.9	7.5	
Supply current - AC signal	All channels switching with square wave clock input; CL = 15 pF	1 Mbps	I_{CC1}		5	7	
			I_{CC2}		4.5	6.9	
		10 Mbps	I_{CC1}		5.5	7.5	
			I_{CC2}		6.5	9.2	
		50 Mbps	I_{CC1}		7.7	10	
			I_{CC2}		15.5	19.6	
ISO6762							

V_{CC1} = V_{CC2} = 3.3 V ±10% (over recommended operating conditions unless otherwise noted).

PARAMETER	TEST CONDITIONS		SUPPLY CURRENT	MIN	TYP	MAX	UNIT
Supply current - DC signal	VI = VCC1 (ISO6762); VI = 0 V (ISO6762 with F suffix)		I_{CC1}		2.7	4.1	mA
			I_{CC2}		3.3	5.2	
	VI = 0 V (ISO6762); VI = VCC1 (ISO6762 with F suffix)		I_{CC1}		6.9	9.6	
			I_{CC2}		5.6	8.2	
Supply current - AC signal	All channels switching with square wave clock input; CL = 15 pF	1 Mbps	I_{CC1}		4.9	6.9	
			I_{CC2}		4.6	6.9	
		10 Mbps	I_{CC1}		5.7	7.9	
			I_{CC2}		6.2	8.8	
		50 Mbps	I_{CC1}		9.6	12.4	
			I_{CC2}		13.5	17.1	
ISO6763							
Supply current - DC signal	V_I = V_{CCI} (ISO6763); V_I = 0 V (ISO6763 with F suffix)		I_{CC1}, I_{CC2}		3	4.6	mA
	V_I = 0 V (ISO6763); V_I = V_{CCI} (ISO6763 with F suffix)		I_{CC1}, I_{CC2}		6.2	8.9	
Supply current - AC signal	All channels switching with square wave clock input; C_L = 15 pF	1 Mbps	I_{CC1}, I_{CC2}		4.8	6.9	
		10 Mbps	I_{CC1}, I_{CC2}		6	8.4	
		50 Mbps	I_{CC1}, I_{CC2}		11.6	14.7	

6.13 Electrical Characteristics—2.5-V Supply

V_{CC1} = V_{CC2} = 2.5 V ±10% (over recommended operating conditions unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	I_{OH} = -1mA ; See 図 7-1	V_{CCO} - 0.1			V
V_{OL}	Low-level output voltage	I_{OL} = 1mA ; See 図 7-1			0.1	V
$V_{IT+(IN)}$	Rising input switching threshold				0.7 x V_{CCI} (1)	V
$V_{IT-(IN)}$	Falling input switching threshold		0.3 x V_{CCI}			V
$V_{I(HYS)}$	Input threshold voltage hysteresis		0.1 x V_{CCI}			V
I_{IH}	High-level input current	V_{IH} = V_{CCI} (1) at INx			10	µA
I_{IL}	Low-level input current	V_{IL} = 0 V at INx	-10			µA
CMTI	Common mode transient immunity	V_I = V_{CC} or 0 V, V_{CM} = 1200 V; See 図 7-3	100	150		kV/us
C_i	Input Capacitance(2)	V_I = V_{CC}/ 2 + 0.4×sin(2πft), f = 2 MHz, V_{CC} = 2.5 V		2.8		pF

(1) V_{CCI} = Input-side V_{CC}; V_{CCO} = Output-side V_{CC}
(2) Measured from input pin to same side ground.

6.14 Supply Current Characteristics—2.5-V Supply

V_{CC1} = V_{CC2} = 2.5 V ±10% (over recommended operating conditions unless otherwise noted).

PARAMETER	TEST CONDITIONS		SUPPLY CURRENT	MIN	TYP	MAX	UNIT
ISO6760							
Supply current - DC signal	VI = VCC1 (ISO6760); VI = 0 V (ISO6760 with F suffix)		I_{CC1}		2.2	2.8	mA
			I_{CC2}		3.1	5.1	
	VI = 0 V (ISO6760); VI = VCC1 (ISO6760 with F suffix)		I_{CC1}		8.3	10.8	
			I_{CC2}		3.4	5.6	
Supply current - AC signal	All channels switching with square wave clock input; CL = 15 pF	1 Mbps	I_{CC1}		5.2	6.8	
			I_{CC2}		3.5	5.6	
		10 Mbps	I_{CC1}		5.3	6.9	
			I_{CC2}		5.3	7.7	
		50 Mbps	I_{CC1}		5.7	7.5	
			I_{CC2}		13.2	16.9	
ISO6761							
Supply current - DC signal	VI = VCC1 (ISO6761); VI = 0 V (ISO6761 with F suffix)		I_{CC1}		2.4	3.5	mA
			I_{CC2}		3.6	5.7	
	VI = 0 V (ISO6761); VI = VCC1 (ISO6761 with F suffix)		I_{CC1}		7.5	10.3	
			I_{CC2}		4.9	7.5	
Supply current - AC signal	All channels switching with square wave clock input; CL = 15 pF	1 Mbps	I_{CC1}		5	6.9	
			I_{CC2}		4.4	6.8	
		10 Mbps	I_{CC1}		5.3	7.3	
			I_{CC2}		5.9	8.5	
		50 Mbps	I_{CC1}		7	9.3	
			I_{CC2}		12.7	16.3	
ISO6762							

V_{CC1} = V_{CC2} = 2.5 V ±10% (over recommended operating conditions unless otherwise noted).

PARAMETER	TEST CONDITIONS		SUPPLY CURRENT	MIN	TYP	MAX	UNIT
Supply current - DC signal	VI = VCC1 (ISO6762); VI = 0 V (ISO6762 with F suffix)		I_{CC1}		2.7	4	mA
			I_{CC2}		3.3	5.2	
	VI = 0 V (ISO6762); VI = VCC1 (ISO6762 with F suffix)		I_{CC1}		6.9	9.6	
			I_{CC2}		5.6	8.2	
Supply current - AC signal	All channels switching with square wave clock input; CL = 15 pF	1 Mbps	I_{CC1}		4.9	6.9	
			I_{CC2}		4.6	6.8	
		10 Mbps	I_{CC1}		5.5	7.6	
			I_{CC2}		5.8	8.2	
		50 Mbps	I_{CC1}		8.4	11	
			I_{CC2}		11.2	14.5	
ISO6763							
Supply current - DC signal	V_I = V_{CCI} (ISO6763); V_I = 0 V (ISO6763 with F suffix)		I_{CC1}, I_{CC2}		3	4.6	mA
	V_I = 0 V (ISO6763); V_I = V_{CCI} (ISO6763 with F suffix)		I_{CC1}, I_{CC2}		6.2	8.9	
Supply current - AC signal	All channels switching with square wave clock input; C_L = 15 pF	1 Mbps	I_{CC1}, I_{CC2}		4.7	6.9	
		10 Mbps	I_{CC1}, I_{CC2}		5.6	7.9	
		50 Mbps	I_{CC1}, I_{CC2}		9.8	12.7	

6.15 Electrical Characteristics—1.8-V Supply

V_{CC1} = V_{CC2} = 1.8 V ±10% (over recommended operating conditions unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	I_{OH} = -1mA ; See 図 7-1	V_{CCO} - 0.1			V
V_{OL}	Low-level output voltage	I_{OL} = 1mA ; See 図 7-1			0.1	V
$V_{IT+(IN)}$	Rising input switching threshold				0.7 x V_{CCI} (1)	V
$V_{IT-(IN)}$	Falling input switching threshold		0.3 x V_{CCI}			V
$V_{I(HYS)}$	Input threshold voltage hysteresis		0.1 x V_{CCI}			V
I_{IH}	High-level input current	V_{IH} = V_{CCI} (1) at INx			10	µA
I_{IL}	Low-level input current	V_{IL} = 0 V at INx	-10			µA
CMTI	Common mode transient immunity	V_I = V_{CC} or 0 V, V_{CM} = 1200 V; See 図 7-3	50	75		kV/us
C_i	Input Capacitance(2)	V_I = V_{CC}/ 2 + 0.4×sin(2πft), f = 2 MHz, V_{CC} = 1.8 V		2.8		pF

(1) V_{CCI} = Input-side V_{CC}; V_{CCO} = Output-side V_{CC}
(2) Measured from input pin to same side ground.

6.16 Supply Current Characteristics—1.8-V Supply

V_{CC1} = V_{CC2} = 1.8 V ±10% (over recommended operating conditions unless otherwise noted).

PARAMETER	TEST CONDITIONS		SUPPLY CURRENT	MIN	TYP	MAX	UNIT
ISO6760							
Supply current - DC signal	VI = VCC1 (ISO6760); VI = 0 V (ISO6760 with F suffix)		I_{CC1}		1.5	2.1	mA
			I_{CC2}		3	5.1	
	VI = 0 V (ISO6760); VI = VCC1 (ISO6760 with F suffix)		I_{CC1}		7.3	10.3	
			I_{CC2}		3.3	5.6	
Supply current - AC signal	All channels switching with square wave clock input; CL = 15 pF	1 Mbps	I_{CC1}		4.4	6.2	
			I_{CC2}		3.3	5.5	
		10 Mbps	I_{CC1}		4.5	6.3	
			I_{CC2}		4.6	7	
		50 Mbps	I_{CC1}		4.8	6.7	
			I_{CC2}		10.1	13	
ISO6761							
Supply current - DC signal	VI = VCC1 (ISO6761); VI = 0 V (ISO6761 with F suffix)		I_{CC1}		1.8	2.9	mA
			I_{CC2}		3.4	5.7	
	VI = 0 V (ISO6761); VI = VCC1 (ISO6761 with F suffix)		I_{CC1}		6.7	9.8	
			I_{CC2}		4.6	7.4	
Supply current - AC signal	All channels switching with square wave clock input; CL = 15 pF	1 Mbps	I_{CC1}		4.3	6.4	
			I_{CC2}		4.1	6.7	
		10 Mbps	I_{CC1}		4.6	6.7	
			I_{CC2}		5.2	7.9	
		50 Mbps	I_{CC1}		5.8	8.1	
			I_{CC2}		9.9	13	
ISO6762							

V_{CC1} = V_{CC2} = 1.8 V ±10% (over recommended operating conditions unless otherwise noted).

PARAMETER	TEST CONDITIONS		SUPPLY CURRENT	MIN	TYP	MAX	UNIT
Supply current - DC signal	VI = VCC1 (ISO6762); VI = 0 V (ISO6762 with F suffix)		I_{CC1}		2.2	3.6	mA
			I_{CC2}		3	5	
	VI = 0 V (ISO6762); VI = VCC1 (ISO6762 with F suffix)		I_{CC1}		6.2	9.2	
			I_{CC2}		5.1	8	
Supply current - AC signal	All channels switching with square wave clock input; CL = 15 pF	1 Mbps	I_{CC1}		4.3	6.5	
			I_{CC2}		4.2	6.6	
		10 Mbps	I_{CC1}		4.7	7	
			I_{CC2}		5	7.6	
		50 Mbps	I_{CC1}		6.8	9.3	
			I_{CC2}		8.9	11.8	
ISO6763							
Supply current - DC signal	V_I = V_{CCI} (ISO6763); V_I = 0 V (ISO6763 with F suffix)		I_{CC1}, I_{CC2}		2.6	4.3	mA
	V_I = 0 V (ISO6763); V_I = V_{CCI} (ISO6763 with F suffix)		I_{CC1}, I_{CC2}		5.7	8.6	
Supply current - AC signal	All channels switching with square wave clock input; C_L = 15 pF	1 Mbps	I_{CC1}, I_{CC2}		4.2	6.5	
		10 Mbps	I_{CC1}, I_{CC2}		4.9	7.3	
		50 Mbps	I_{CC1}, I_{CC2}		7.9	10.5	

6.17 Switching Characteristics—5-V Supply

V_{CC1} = V_{CC2} = 5 V ±10% (over recommended operating conditions unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
ISO676x							
t_{PLH}, t_{PHL}	Propagation delay time	Propagation delay time	See 図 7-1		11	18	ns
PWD	Pulse width distortion(1) $\lvert t_{PHL} - t_{PLH} \rvert$	Pulse width distortion(1) $\lvert t_{PHL} - t_{PLH} \rvert$				7	ns
$t_{sk(o)}$	Channel-to-channel output skew time(2)	Channel-to-channel output skew time(2)	Same-direction channels			6	ns
$t_{sk(pp)}$	Part-to-part skew time(3)	Part-to-part skew time(3)				6	ns
t_r	Output signal rise time	Output signal rise time	See 図 7-1			4.5	ns
t_f	Output signal fall time	Output signal fall time				4.5	ns
tPU	Time from UVLO to valid output data	Time from UVLO to valid output data				300	us
t_{DO}	Default output delay time from input power loss	Default output delay time from input power loss	Measured from the time VCC goes below 1.2V. See 図 7-2		0.1	0.3	us
t_{ie}	Time interval error	Time interval error	2^{16} – 1 PRBS data at 50 Mbps		1		ns

(1) Also known as pulse skew.
(2) $t_{sk(o)}$ is the skew between outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical loads.
(3) $t_{sk(pp)}$ is the magnitude of the difference in propagation delay times between any terminals of different devices switching in the same direction while operating at identical supply voltages, temperature, input signals and loads.

6.18 Switching Characteristics—3.3-V Supply

V_{CC1} = V_{CC2} = 3.3 V ±10% (over recommended operating conditions unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
ISO676x							
t_{PLH}, t_{PHL}	Propagation delay time	Propagation delay time	See 図 7-1		11	18	ns
PWD	Pulse width distortion(1) $\lvert t_{PHL} - t_{PLH} \rvert$	Pulse width distortion(1) $\lvert t_{PHL} - t_{PLH} \rvert$				7	ns
$t_{sk(o)}$	Channel-to-channel output skew time(2)	Channel-to-channel output skew time(2)	Same-direction channels			6	ns
$t_{sk(pp)}$	Part-to-part skew time(3)	Part-to-part skew time(3)				7	ns
t_r	Output signal rise time	Output signal rise time	See 図 7-1			3.2	ns
t_f	Output signal fall time	Output signal fall time				3.2	ns
tPU	Time from UVLO to valid output data	Time from UVLO to valid output data				300	us
t_{DO}	Default output delay time from input power loss	Default output delay time from input power loss	Measured from the time VCC goes below 1.2V. See 図 7-2		0.1	0.3	us
t_{ie}	Time interval error	Time interval error	2^{16} – 1 PRBS data at 50 Mbps		1		ns

(1) Also known as pulse skew.
(2) $t_{sk(o)}$ is the skew between outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical loads.
(3) $t_{sk(pp)}$ is the magnitude of the difference in propagation delay times between any terminals of different devices switching in the same direction while operating at identical supply voltages, temperature, input signals and loads.

6.19 Switching Characteristics—2.5-V Supply

V_{CC1} = V_{CC2} = 2.5 V ±10% (over recommended operating conditions unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
ISO676x							
t_{PLH}, t_{PHL}	Propagation delay time	Propagation delay time	See 図 7-1		12	20.5	ns
PWD	Pulse width distortion(1) $\lvert t_{PHL} - t_{PLH} \rvert$	Pulse width distortion(1) $\lvert t_{PHL} - t_{PLH} \rvert$				7.1	ns
$t_{sk(o)}$	Channel-to-channel output skew time(2)	Channel-to-channel output skew time(2)	Same-direction channels			6	ns
$t_{sk(pp)}$	Part-to-part skew time(3)	Part-to-part skew time(3)				7	ns
t_r	Output signal rise time	Output signal rise time	See 図 7-1			4	ns
t_f	Output signal fall time	Output signal fall time				4	ns
tPU	Time from UVLO to valid output data	Time from UVLO to valid output data				300	us
t_{DO}	Default output delay time from input power loss	Default output delay time from input power loss	Measured from the time VCC goes below 1.2V. See 図 7-2		0.1	0.3	us
t_{ie}	Time interval error	Time interval error	2^{16} – 1 PRBS data at 50 Mbps		1		ns

(1) Also known as pulse skew.
(2) $t_{sk(o)}$ is the skew between outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical loads.
(3) $t_{sk(pp)}$ is the magnitude of the difference in propagation delay times between any terminals of different devices switching in the same direction while operating at identical supply voltages, temperature, input signals and loads.

6.20 Switching Characteristics—1.8-V Supply

V_{CC1} = V_{CC2} = 1.8 V ±5% (over recommended operating conditions unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
ISO676x							
t_{PLH}, t_{PHL}	Propagation delay time	Propagation delay time	See 図 7-1		15	24	ns
PWD	Pulse width distortion $\|t_{PHL} - t_{PLH}\|$	Pulse width distortion $\|t_{PHL} - t_{PLH}\|$				8.2	ns
$t_{sk(o)}$	Channel-to-channel output skew time(1)	Channel-to-channel output skew time(1)	Same-direction channels			6	ns
$t_{sk(pp)}$	Part-to-part skew time(2)	Part-to-part skew time(2)				8.8	ns
t_r	Output signal rise time	Output signal rise time	See 図 7-1			4.7	ns
t_f	Output signal fall time	Output signal fall time				4.7	ns
t_{PU}	Time from UVLO to valid output data	Time from UVLO to valid output data				300	us
t_{DO}	Default output delay time from input power loss	Default output delay time from input power loss	Measured from the time VCC goes below 1.2V. See 図 7-2		0.1	0.3	us
t_{ie}	Time interval error	Time interval error	2^{16} – 1 PRBS data at 50 Mbps		1		ns

(1) $t_{sk(o)}$ is the skew between outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical loads.

(2) $t_{sk(pp)}$ is the magnitude of the difference in propagation delay times between any terminals of different devices switching in the same direction while operating at identical supply voltages, temperature, input signals and loads.

6.21 絶縁特性曲線

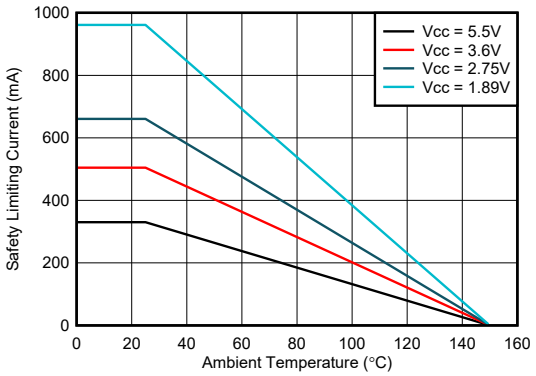


図 6-1. DW-16 パッケージでの安全限界電流の熱特性低下曲線

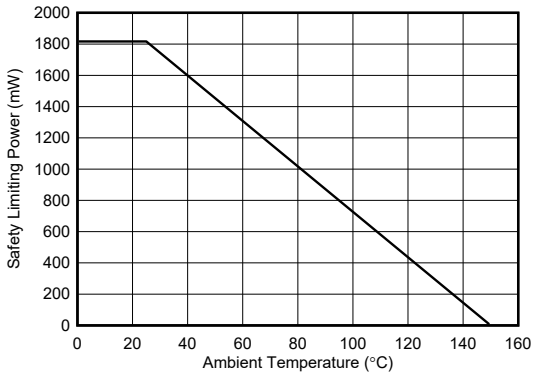
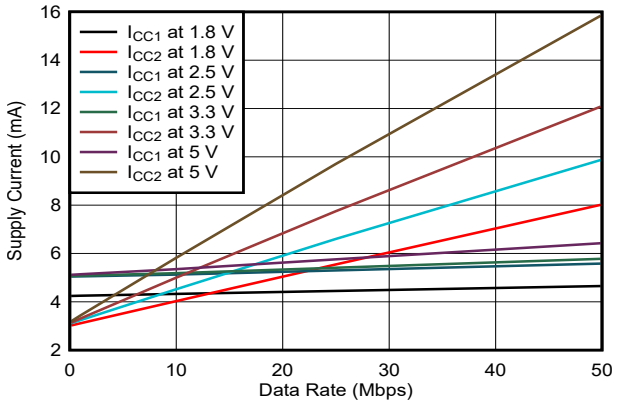


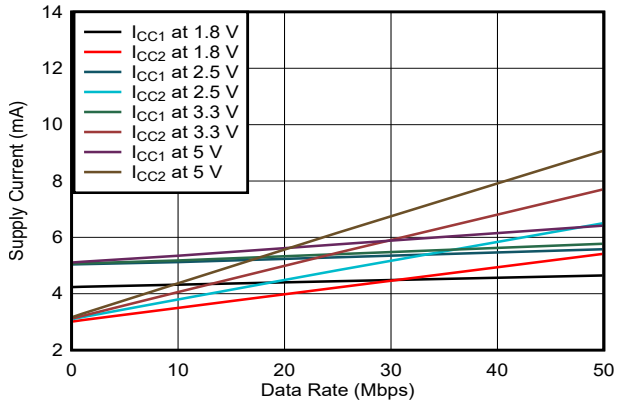
図 6-2. DW-16 パッケージでの安全限界電力の熱特性低下曲線

6.22 Typical Characteristics



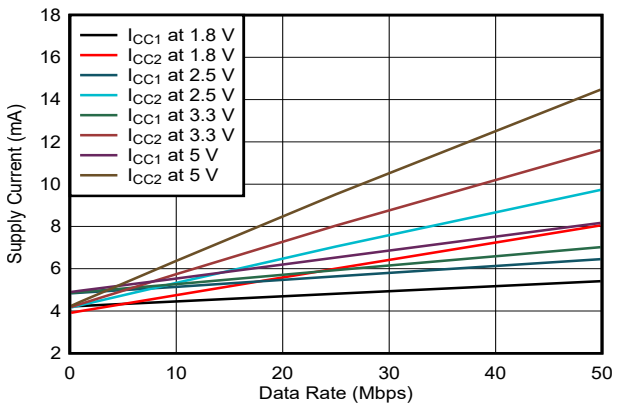
T_A = 25°C C_L = 15 pF

図 6-3. ISO6760 Supply Current vs Data Rate (With 15-pF Load)



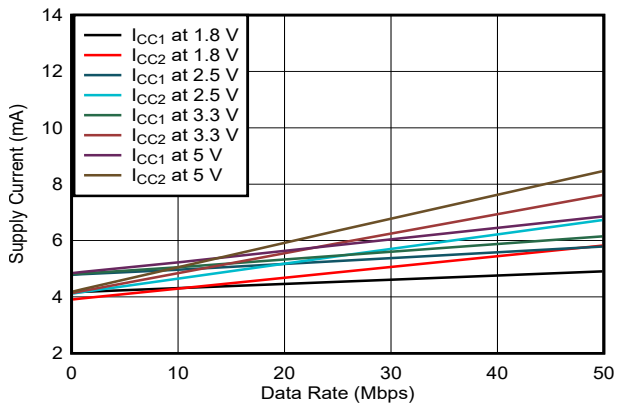
T_A = 25°C C_L = No Load

図 6-4. ISO6760 Supply Current vs Data Rate (With No Load)



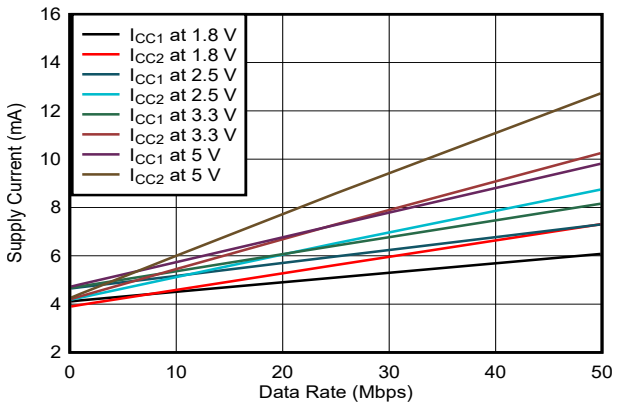
T_A = 25°C C_L = 15 pF

図 6-5. ISO6761 Supply Current vs Data Rate (With 15-pF Load)



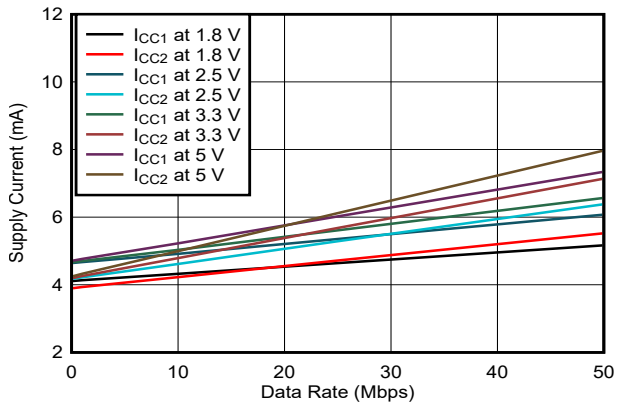
T_A = 25°C C_L = No Load

図 6-6. ISO6761 Supply Current vs Data Rate (With No Load)



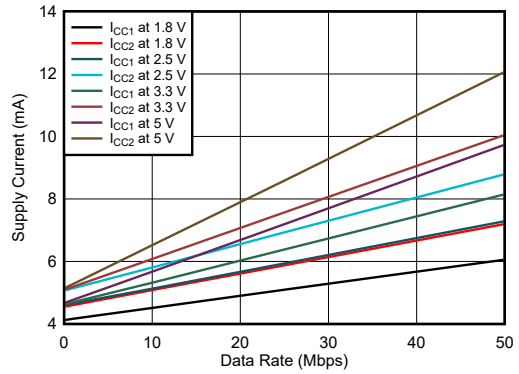
T_A = 25°C C_L = 15 pF

図 6-7. ISO6762 Supply Current vs Data Rate (With 15-pF Load)



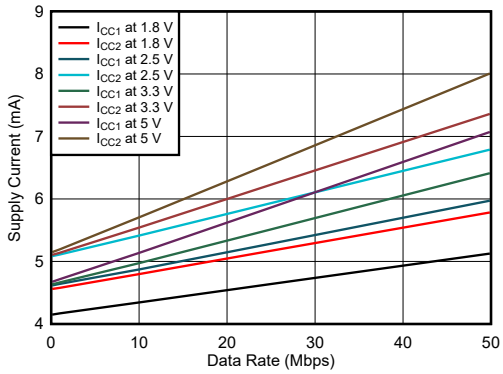
T_A = 25°C C_L = No Load

図 6-8. ISO6762 Supply Current vs Data Rate (With No Load)



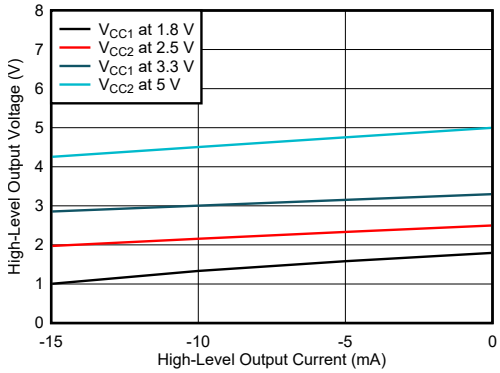
T_A = 25°C C_L = 15 pF

図 6-9. ISO6763 Supply Current vs Data Rate (With 15-pF Load)



T_A = 25°C C_L = No Load

図 6-10. ISO6763 Supply Current vs Data Rate (With No Load)



T_A = 25°C

図 6-11. High-Level Output Voltage vs High-level Output Current

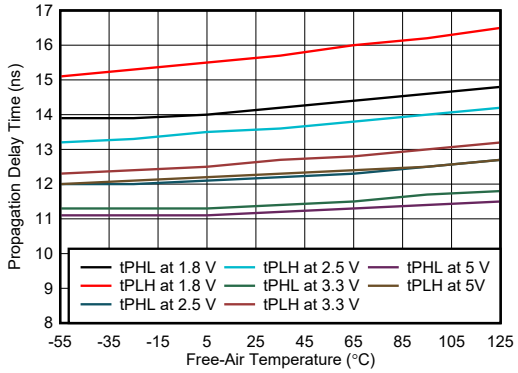


図 6-12. Propagation Delay Time vs Free-Air Temperature

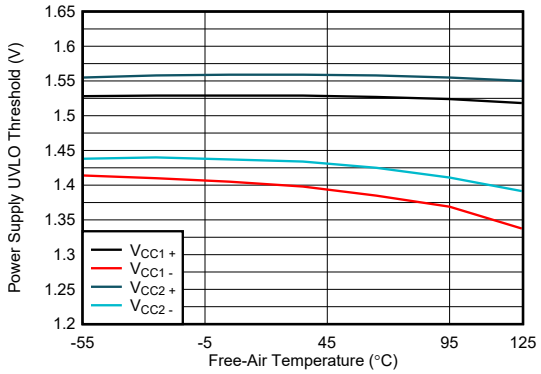
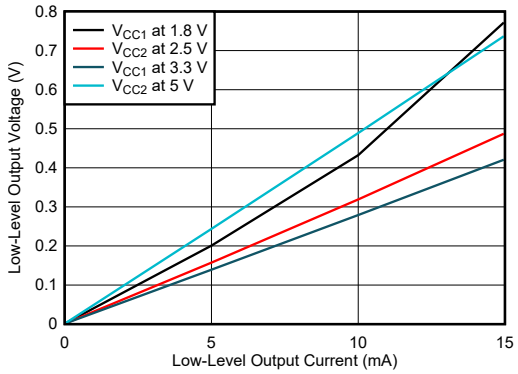


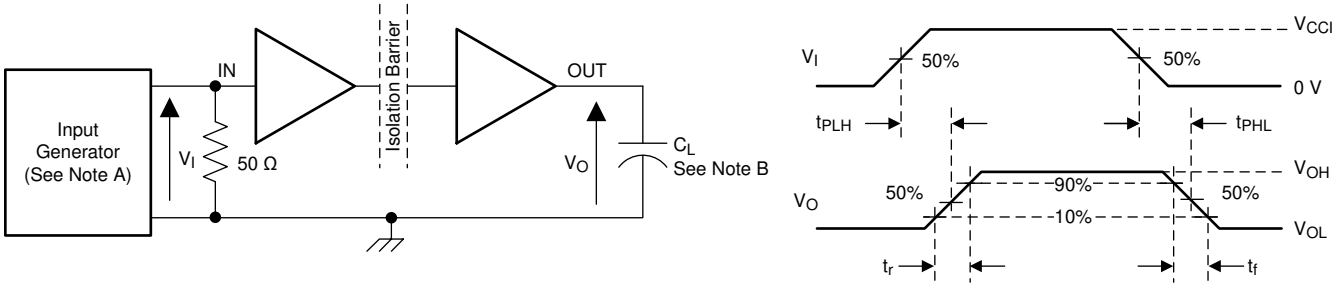
図 6-13. Power Supply Undervoltage Threshold vs Free-Air Temperature



T_A = 25°C

図 6-14. Low-Level Output Voltage vs Low-Level Output Current

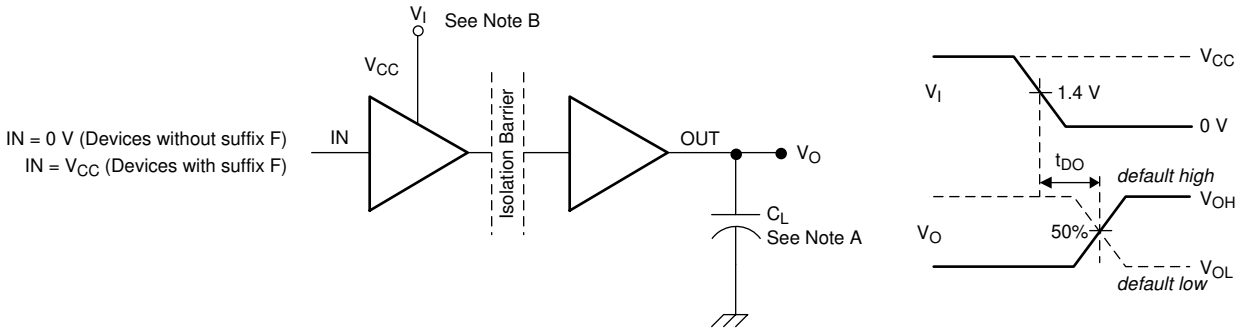
7 Parameter Measurement Information



A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 50 kHz, 50% duty cycle, t_r ≤ 3 ns, t_f ≤ 3ns, Z_O = 50 Ω. At the input, 50 Ω resistor is required to terminate Input Generator signal. It is not needed in actual application.

B. C_L = 15 pF and includes instrumentation and fixture capacitance within ±20%.

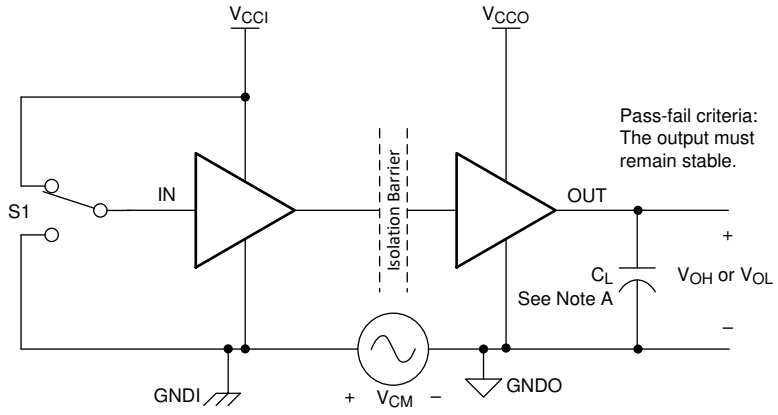
図 7-1. Switching Characteristics Test Circuit and Voltage Waveforms



A. C_L = 15 pF and includes instrumentation and fixture capacitance within ±20%.

B. Power Supply Ramp Rate = 10 mV/ns

図 7-2. Default Output Delay Time Test Circuit and Voltage Waveforms



A. C_L = 15 pF and includes instrumentation and fixture capacitance within ±20%.

B. For optimized CMTI performance, a 0.1 µF + 1 µF decoupling capacitor should be placed close to V_{CC1} and V_{CC2}. Please see セクション 11.2 for capacitor placement details. A recommended 0.1µF capacitor is LLL185R71A104MA11L (CAP CER 0.1UF 10V X7R 0306 - LW Reversed Low ESL Chip Ceramic Capacitors) or equivalent.

図 7-3. Common-Mode Transient Immunity Test Circuit

8 Detailed Description

8.1 Overview

The ISO676x family of devices have an ON-OFF keying (OOK) modulation scheme to transmit the digital data across a silicon dioxide based isolation barrier. The transmitter sends a high frequency carrier across the barrier to represent one digital state and sends no signal to represent the other digital state. The receiver demodulates the signal after advanced signal conditioning and produces the output through a buffer stage. If the ENx pin is low then the output goes to high impedance. The ISO676x devices also incorporate advanced circuit techniques to maximize the CMTI performance and minimize the radiated emissions due to the high frequency carrier and IO buffer switching. The conceptual block diagram of a digital capacitive isolator, 図 8-1, shows a functional block diagram of a typical channel.

8.2 Functional Block Diagram

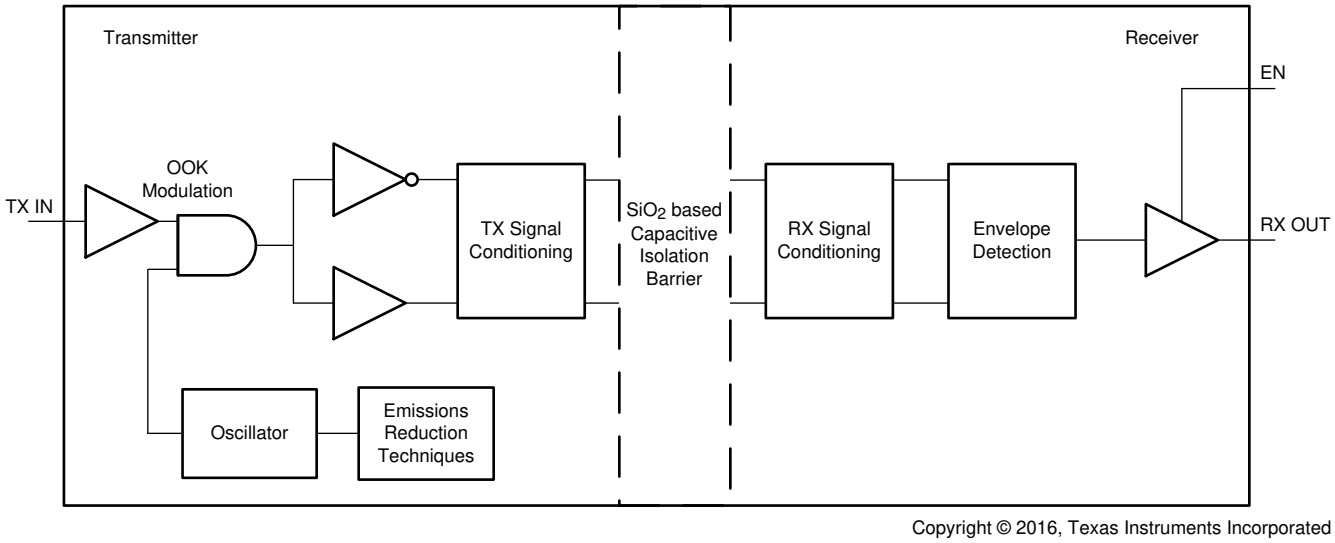


図 8-1. Conceptual Block Diagram of a Digital Capacitive Isolator

図 8-2 shows a conceptual detail of how the ON-OFF keying scheme works.

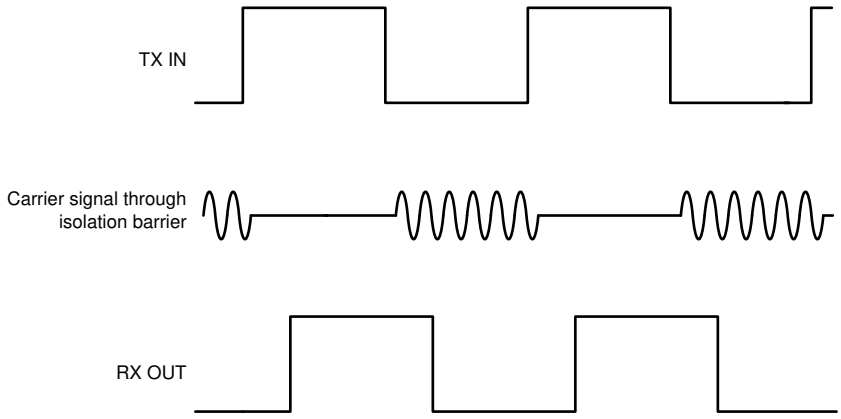


図 8-2. On-Off Keying (OOK) Based Modulation Scheme

8.3 Feature Description

Device Features provides an overview of the device features.

表 8-1. Device Features

PART NUMBER	CHANNEL DIRECTION	MAXIMUM DATA RATE	DEFAULT OUTPUT	PACKAGE	RATED ISOLATION(1)
ISO6760	6 Forward, 0 Reverse	50 Mbps	High	DW-16	5000 V_{RMS} / 7071 V_{PK}
ISO6760F	6 Forward, 0 Reverse	50 Mbps	Low	DW-16	5000 V_{RMS} / 7071 V_{PK}
ISO6761	5 Forward, 1 Reverse	50 Mbps	High	DW-16	5000 V_{RMS} / 7071 V_{PK}
ISO6761F	5 Forward, 1 Reverse	50 Mbps	Low	DW-16	5000 V_{RMS} / 7071 V_{PK}
ISO6762	4 Forward, 2 Reverse	50 Mbps	High	DW-16	5000 V_{RMS} / 7071 V_{PK}
ISO6762F	4 Forward, 2 Reverse	50 Mbps	Low	DW-16	5000 V_{RMS} / 7071 V_{PK}
ISO6763	3 Forward, 3 Reverse	50 Mbps	High	DW-16	5000 V_{RMS} / 7071 V_{PK}
ISO6763F	3 Forward, 3 Reverse	50 Mbps	Low	DW-16	5000 V_{RMS} / 7071 V_{PK}

(1) See for detailed isolation ratings.

8.3.1 Electromagnetic Compatibility (EMC) Considerations

Many applications in harsh industrial environment are sensitive to disturbances such as electrostatic discharge (ESD), electrical fast transient (EFT), surge and electromagnetic emissions. These electromagnetic disturbances are regulated by international standards such as IEC 61000-4-x and CISPR 32. Although system-level performance and reliability depends, to a large extent, on the application board design and layout, the ISO676x family of devices incorporates many chip-level design improvements for overall system robustness. Some of these improvements include:

- Robust ESD protection cells for input and output signal pins and inter-chip bond pads.
- Low-resistance connectivity of ESD cells to supply and ground pins.
- Enhanced performance of high voltage isolation capacitor for better tolerance of ESD, EFT and surge events.
- Bigger on-chip decoupling capacitors to bypass undesirable high energy signals through a low impedance path.
- PMOS and NMOS devices isolated from each other by using guard rings to avoid triggering of parasitic SCRs.
- Reduced common mode currents across the isolation barrier by ensuring purely differential internal operation.

8.4 Device Functional Modes

表 8-2 lists the functional modes for the ISO676x devices.

表 8-2. Function Table

V_{CCI} (1)	V_{CCO}	INPUT (INx) (3)	OUTPUT (OUTx)	COMMENTS
PU	PU	H	H	Normal Operation: A channel output assumes the logic state of its input.
		L	L	
		Open	Default	Default mode: When INx is open, the corresponding channel output goes to its default logic state. Default is *High* for ISO676x and *Low* for ISO676x with F suffix.
PD	PU	X	Default	Default mode: When V_{CCI} is unpowered, a channel output assumes the logic state based on the selected default option. Default is *High* for ISO676x and *Low* for ISO676x with F suffix. When V_{CCI} transitions from unpowered to powered-up, a channel output assumes the logic state of the input. When V_{CCI} transitions from powered-up to unpowered, channel output assumes the selected default state.
X	PD	X	Undetermined	When V_{CCO} is unpowered, a channel output is undetermined(2). When V_{CCO} transitions from unpowered to powered-up, a channel output assumes the logic state of the input.

(1) V_{CCI} = Input-side V_{CC}; V_{CCO} = Output-side V_{CC}; PU = Powered up (V_{CC} ≥ 1.71 V); PD = Powered down (V_{CC} ≤ 1.05 V); X = Irrelevant; H = High level; L = Low level ; Z = High Impedance
(2) The outputs are in undetermined state when 1.05 V < V_{CCI}, V_{CCO} < 1.71 V and 1.89 V < V_{CCI}, V_{CCO} < 2.25 V
(3) A strongly driven input signal can weakly power the floating V_{CC} through an internal protection diode and cause undetermined output

8.4.1 Device I/O Schematics

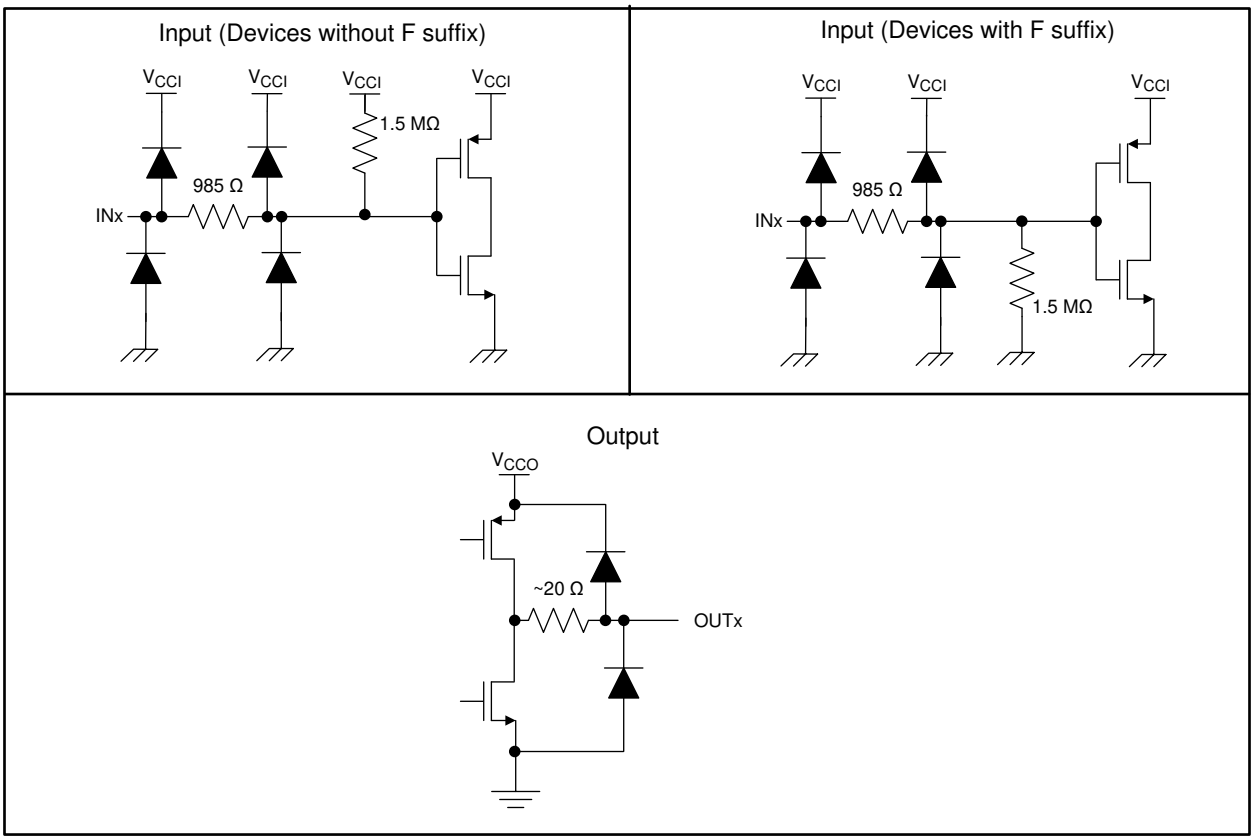


図 8-3. Device I/O Schematics

9 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The ISO676x devices are high-performance, six-channel digital isolators. The ISO676x devices use single-ended CMOS-logic switching technology. The supply voltage range is from 1.71 V to 5.5 V for both supplies, V_{CC1} and V_{CC2}. Since an isolation barrier separates the two sides, each side can be sourced independently with any voltage within recommended operating conditions. As an example, it is possible to supply ISO676x V_{CC1} with 3.3 V (which is within 1.71 V to 5.5 V) and V_{CC2} with 5V (which is also within 1.71 V to 5.5 V). You can use the digital isolator as a logic-level translator in addition to providing isolation. When designing with digital isolators, keep in mind that because of the single-ended design structure, digital isolators do not conform to any specific interface standard and are only intended for isolating single-ended CMOS or TTL digital signal lines. The isolator is typically placed between the data controller (that is, MCU or FPGA), and a data converter or a line transceiver, regardless of the interface type or standard.

9.2 Typical Application

図 9-1 shows the isolated serial-peripheral interface (SPI) and controller-area network (CAN) interface implementation.

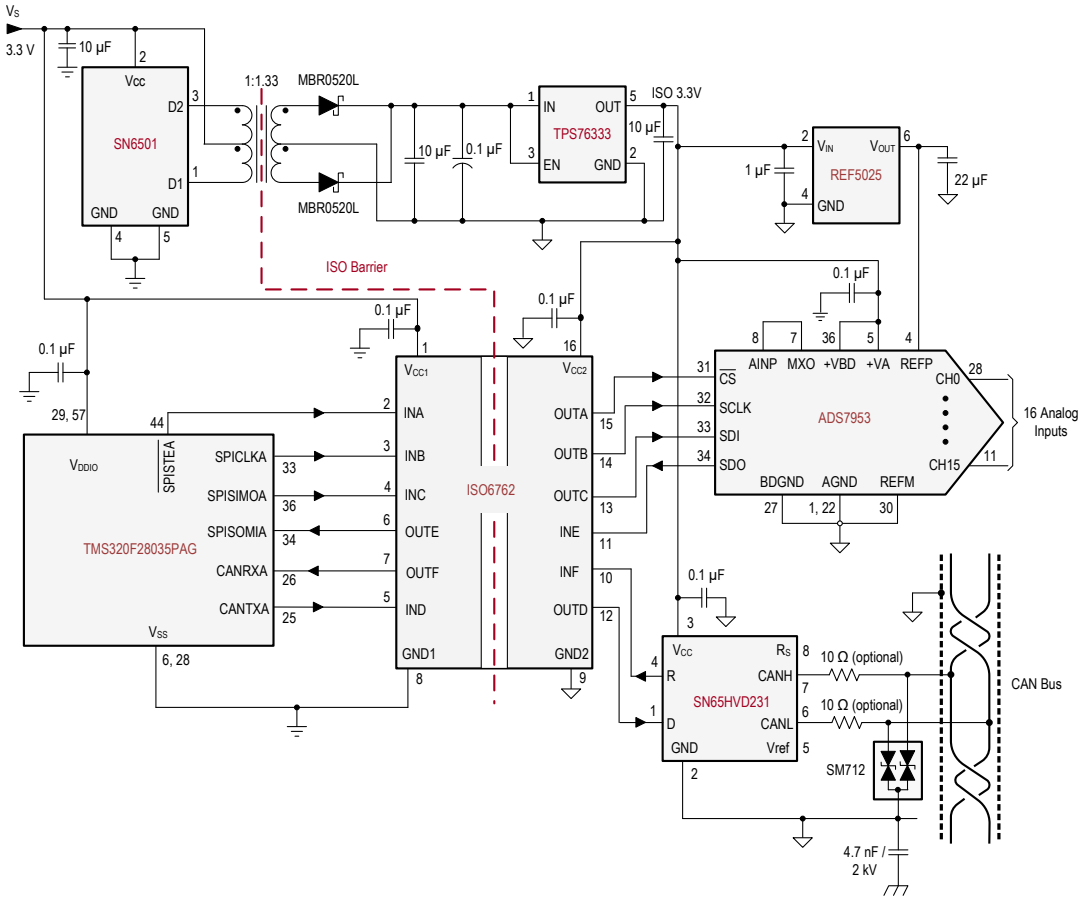


図 9-1. Isolated SPI and CAN Interface

9.2.1 Design Requirements

To design with these devices, use the parameters listed in 表 9-1.

表 9-1. Design Parameters

PARAMETER	VALUE
Supply voltage, V_{CC1} and V_{CC2}	1.71 V to 1.89 V and 2.25 V to 5.5 V
Decoupling capacitor between V_{CC1} and GND1	0.1 µF
Decoupling capacitor from V_{CC2} and GND2	0.1 µF

9.2.2 Detailed Design Procedure

Unlike optocouplers, which require external components to improve performance, provide bias, or limit current, the ISO676x family of devices only require two external bypass capacitors to operate.

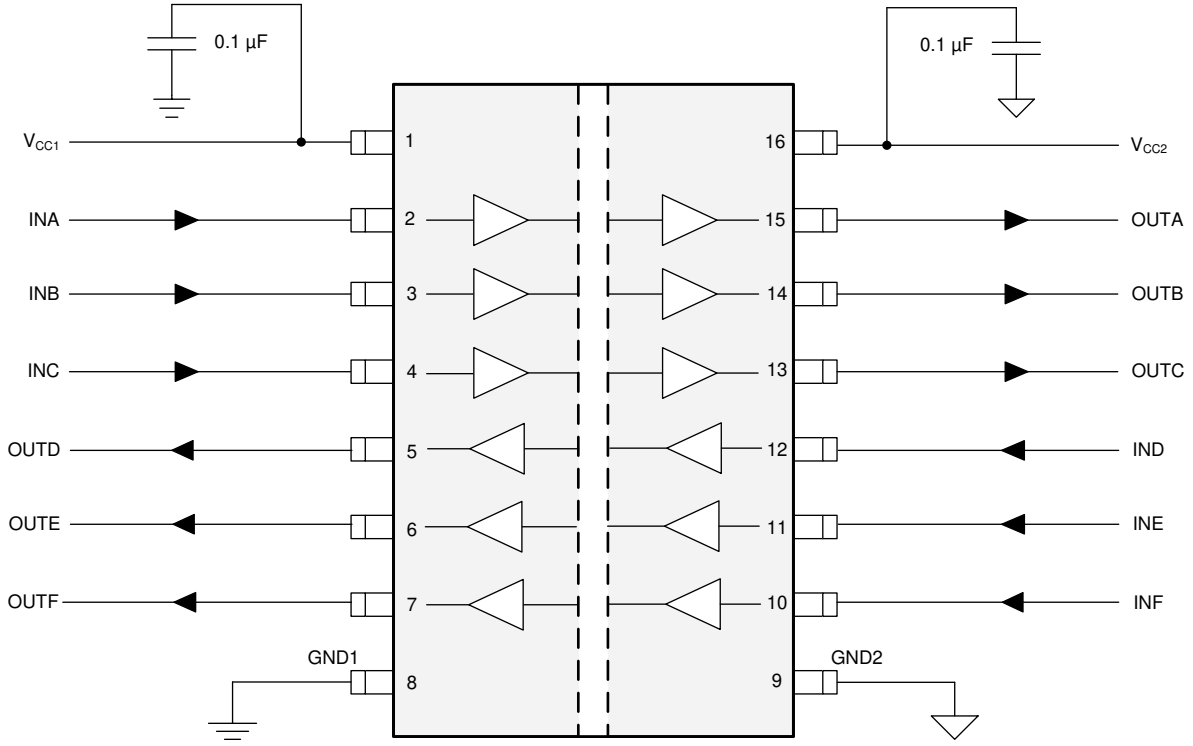


図 9-2. Typical ISO676x Circuit Hook-up

9.2.3 Application Curve

The following typical eye diagrams of the ISO676x family of devices indicates low jitter and wide open eye at the maximum data rate of 50 Mbps.

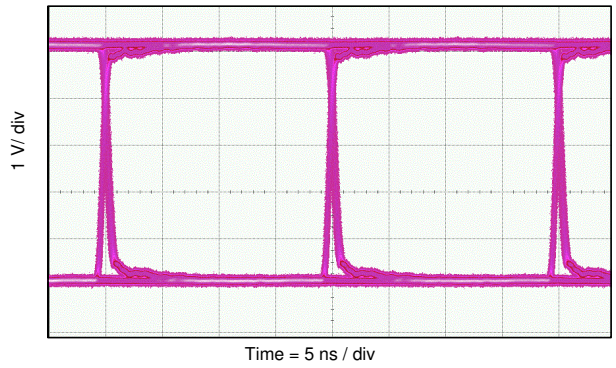


図 9-3. Eye Diagram at 50 Mbps PRBS 2^{16} – 1, 5 V and 25°C

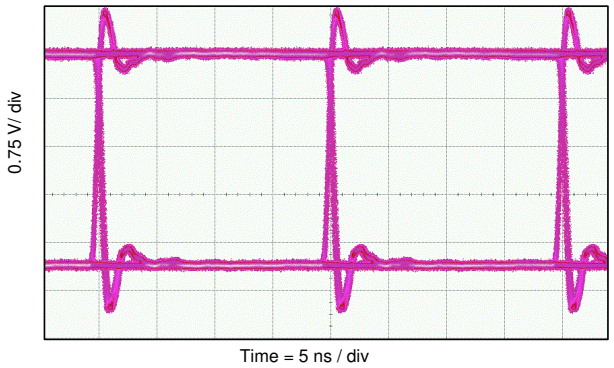


図 9-4. Eye Diagram at 50 Mbps PRBS 2^{16} – 1, 3.3 V and 25°C

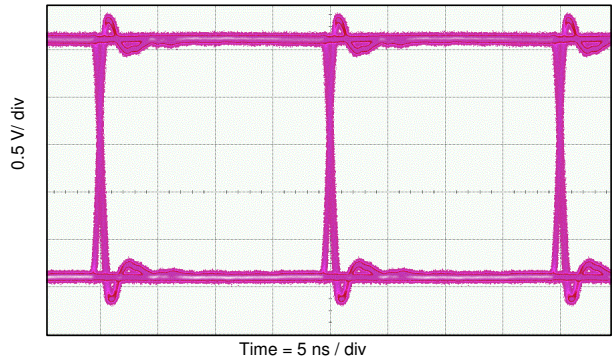


図 9-5. Eye Diagram at 50 Mbps PRBS 2^{16} – 1, 2.5 V and 25°C

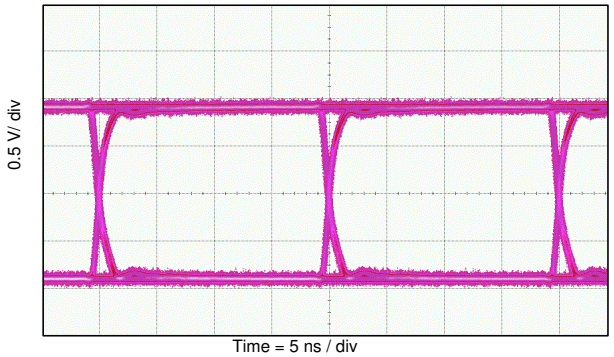


図 9-6. Eye Diagram at 50 Mbps PRBS 2^{16} – 1, 1.8 V and 25°C

9.2.3.1 Insulation Lifetime

Insulation lifetime projection data is collected by using industry-standard Time Dependent Dielectric Breakdown (TDDB) test method. In this test, all pins on each side of the barrier are tied together creating a two-terminal device and high voltage applied between the two sides; See 図 9-7 for TDDB test setup. The insulation breakdown data is collected at various high voltages switching at 60 Hz over temperature. For reinforced insulation, VDE standard requires the use of TDDB projection line with failure rate of less than 1 part per million (ppm). Even though the expected minimum insulation lifetime is 20 years at the specified working isolation voltage, VDE reinforced certification requires additional safety margin of 20% for working voltage and 50% for lifetime which translates into minimum required insulation lifetime of 30 years at a working voltage that's 20% higher than the specified value.

図 9-8 shows the intrinsic capability of the isolation barrier to withstand high voltage stress over its lifetime. Based on the TDDB data, the intrinsic capability of the insulation is 1500 V_{RMS} with a lifetime of 36 years. Other factors, such as package size, pollution degree, material group, etc. can further limit the working voltage of the component. The working voltage of DW-16 package is specified upto 1500 V_{RMS}. At the lower working voltages, the corresponding insulation lifetime is much longer than 36 years.

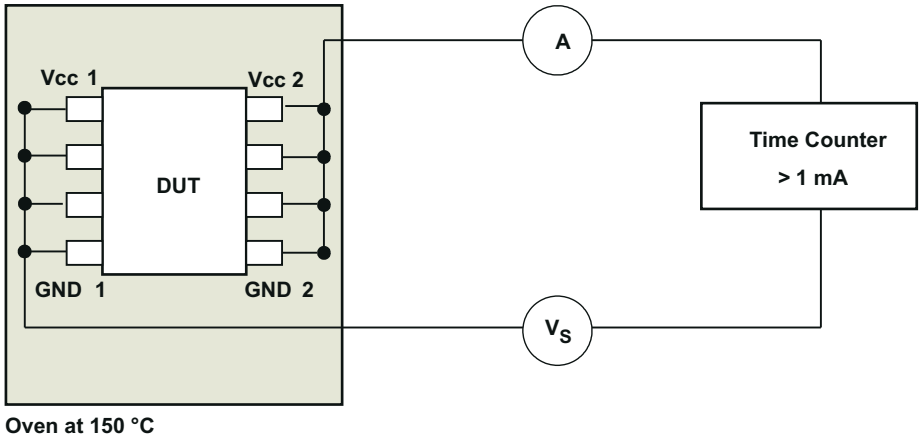


図 9-7. Test Setup for Insulation Lifetime Measurement

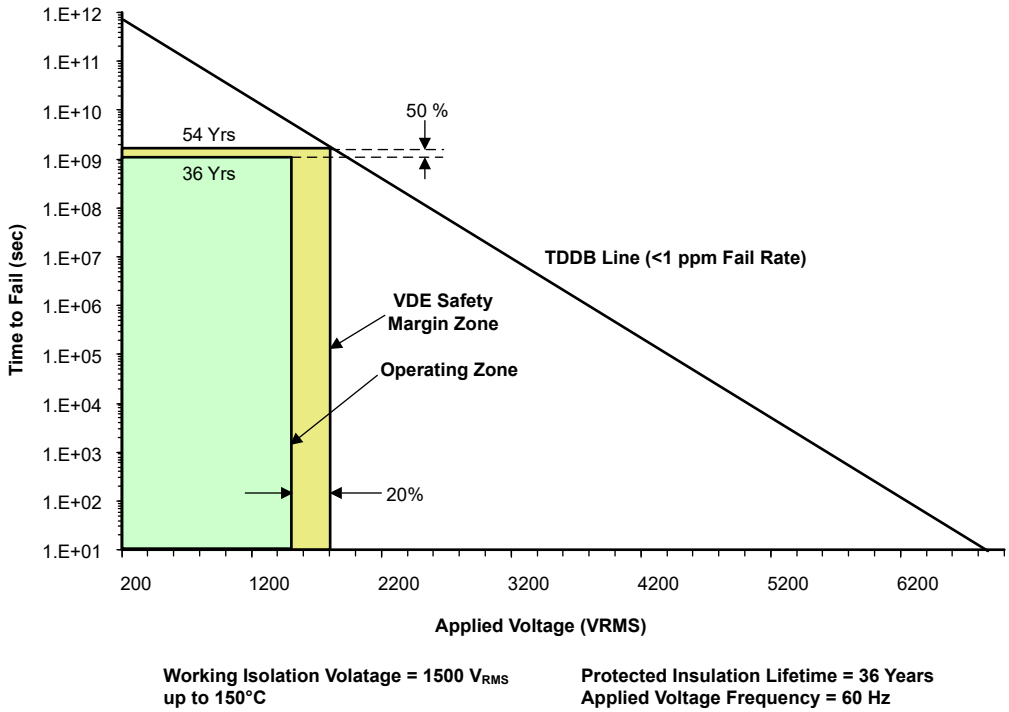


図 9-8. Insulation Lifetime Projection Data

10 Power Supply Recommendations

To help ensure reliable operation at data rates and supply voltages, a 0.1-µF bypass capacitor is recommended at the input and output supply pins (V_{CC1} and V_{CC2}). The capacitors should be placed as close to the supply pins as possible. If only a single primary-side power supply is available in an application, isolated power can be generated for the secondary-side with the help of a transformer driver. For industrial applications, please use Texas Instruments' SN6501 or SN6505B. For such applications, detailed power supply design and transformer selection recommendations are available in *SN6501 Transformer Driver for Isolated Power Supplies* or *SN6505B-Q1 Low-noise, 1-A Transformer Drivers for Isolated Power Supplies*.

11 Layout

11.1 Layout Guidelines

A minimum of two layers is required to accomplish a low EMI PCB design. To further improve EMI, a four layer board can be used (see 図 11-2). Layer stacking for a four layer board should be in the following order (top-to-bottom): high-speed signal layer, ground plane, power plane and low-frequency signal layer.

- Routing the high-speed traces on the top layer avoids the use of vias (and the introduction of their inductances) and allows for clean interconnects between the isolator and the transmitter and receiver circuits of the data link.
- Placing a solid ground plane next to the high-speed signal layer establishes controlled impedance for transmission line interconnects and provides an excellent low-inductance path for the return current flow.
- Placing the power plane next to the ground plane creates additional high-frequency bypass capacitance of approximately 100 pF/inch^2.
- Routing the slower speed control signals on the bottom layer allows for greater flexibility as these signal links usually have margin to tolerate discontinuities such as vias.

If an additional supply voltage plane or signal layer is needed, add a second power or ground plane system to the stack to keep it symmetrical. This makes the stack mechanically stable and prevents it from warping. Also the power and ground plane of each power system can be placed closer together, thus increasing the high-frequency bypass capacitance significantly.

For detailed layout recommendations, refer to the *Digital Isolator Design Guide*.

11.1.1 PCB Material

For digital circuit boards operating below 150 Mbps, (or rise and fall times higher than 1 ns), and trace lengths of up to 10 inches, use standard FR-4 UL94V-0 printed circuit boards. This PCB is preferred over cheaper alternatives due to its lower dielectric losses at high frequencies, less moisture absorption, greater strength and stiffness, and self-extinguishing flammability-characteristics.

11.2 Layout Example

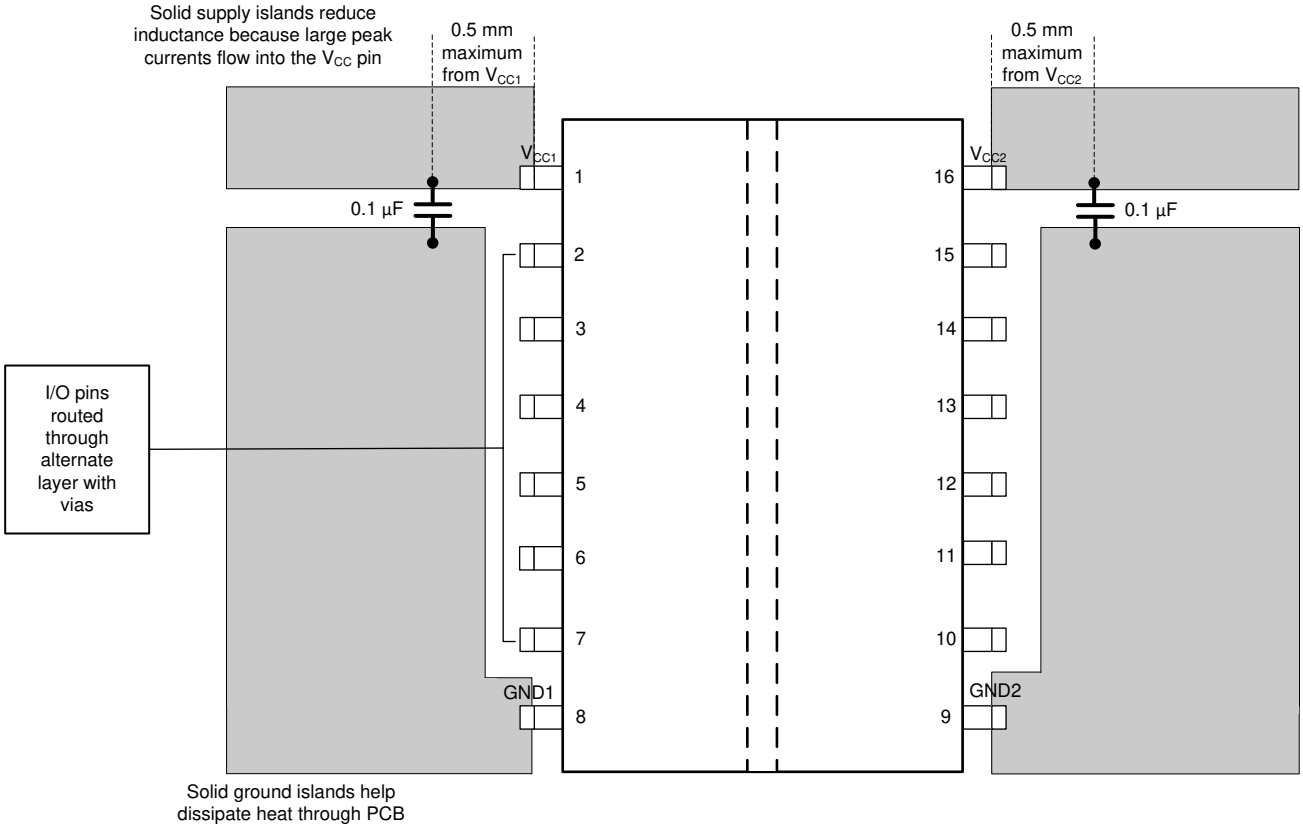


図 11-1. Layout Example

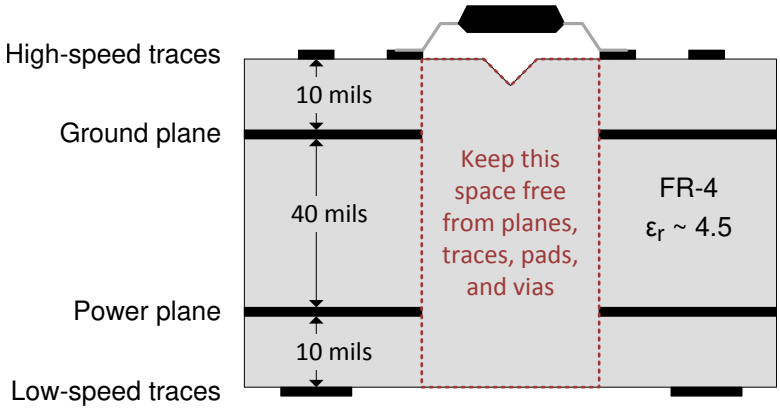


図 11-2. Four Layer Board Layout Example

12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, *Digital Isolator Design Guide*
- Texas Instruments, *Digital Isolator Design Guide*
- Texas Instruments, *Isolation Glossary*
- Texas Instruments, *How to use isolation to improve ESD, EFT, and Surge immunity in industrial systems* application report
- Texas Instruments, *ADS79xx 12/10/8-Bit, 1 MSPS, 16/12/8/4-Channel, Single-Ended, MicroPower, Serial Interface ADCs* data sheet
- Texas Instruments, *DAC161P997 Single-Wire 16-bit DAC for 4- to 20-mA Loops* data sheet
- Texas Instruments, *MSP430G2132Mixed Signal Microcontroller* data sheet
- Texas Instruments, *SN6501 Transformer Driver for Isolated Power Supplies* data sheet
- Texas Instruments, *TPS76333Low-Power 150-mA Low-Dropout Linear Regulators* data sheet

12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

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すべての商標は、それぞれの所有者に帰属します。

12.5 静電気放電に関する注意事項

この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

12.6 用語集

テキサス・インスツルメンツ用語集　　この用語集には、用語や略語の一覧および定義が記載されています。

13 Mechanical, Packaging, and Orderable Information

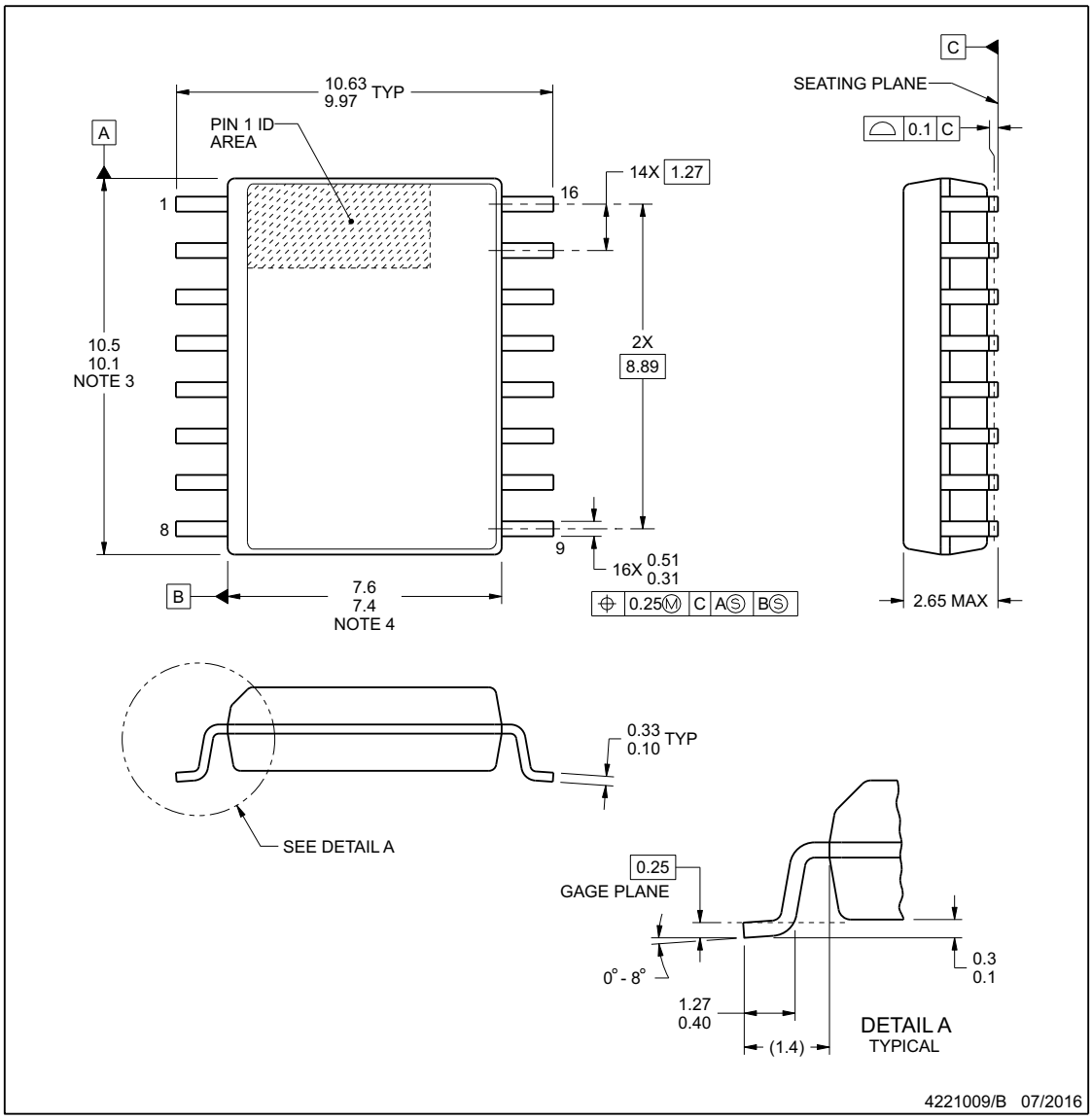
The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGE OUTLINE

DW0016B

SOIC - 2.65 mm max height

SOIC



NOTES:

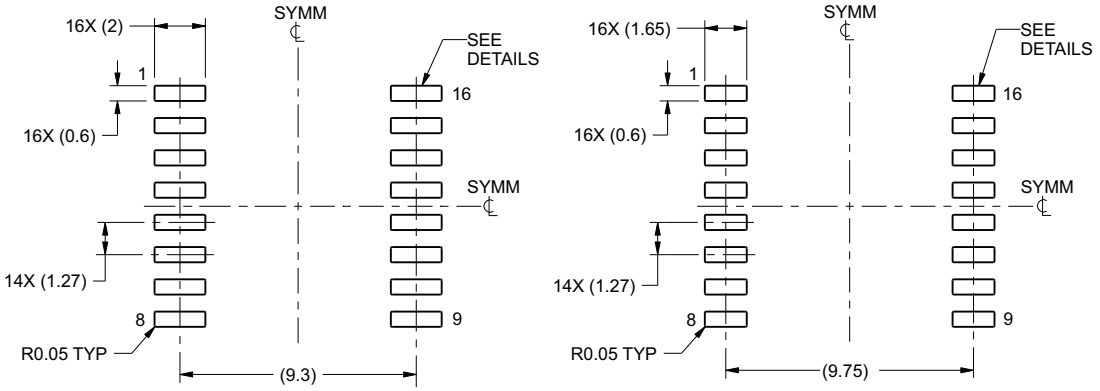
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

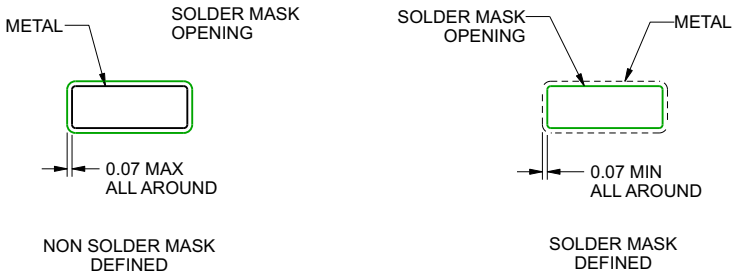
DW0016B

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:4X



SOLDER MASK DETAILS

4221009/B 07/2016

NOTES: (continued)

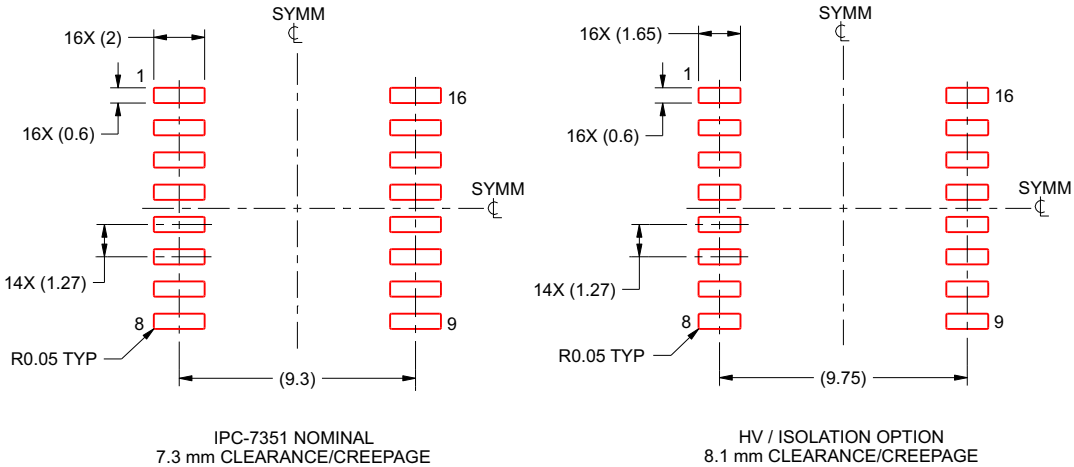
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0016B

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:4X

4221009/B 07/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
ISO6760DWR	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6760
ISO6760DWR.A	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6760
ISO6760DWR.B	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISO6760FDWR	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6760F
ISO6760FDWR.A	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6760F
ISO6760FDWR.B	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISO6761DWR	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6761
ISO6761DWR.A	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6761
ISO6761DWR.B	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISO6761DWRG4	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6761
ISO6761DWRG4.A	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6761
ISO6761DWRG4.B	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISO6761FDWR	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6761F
ISO6761FDWR.A	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6761F
ISO6761FDWR.B	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISO6761FDWRG4	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6761F
ISO6761FDWRG4.A	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6761F
ISO6761FDWRG4.B	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISO6762DWR	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6762
ISO6762DWR.A	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6762
ISO6762DWR.B	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISO6762FDWR	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6762F
ISO6762FDWR.A	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6762F
ISO6762FDWR.B	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISO6763DWR	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6763
ISO6763DWR.A	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6763
ISO6763DWR.B	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISO6763FDWR	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6763F
ISO6763FDWR.A	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO6763F

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
ISO6763FDWR.B	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

OTHER QUALIFIED VERSIONS OF ISO6760, ISO6761, ISO6762, ISO6763 :

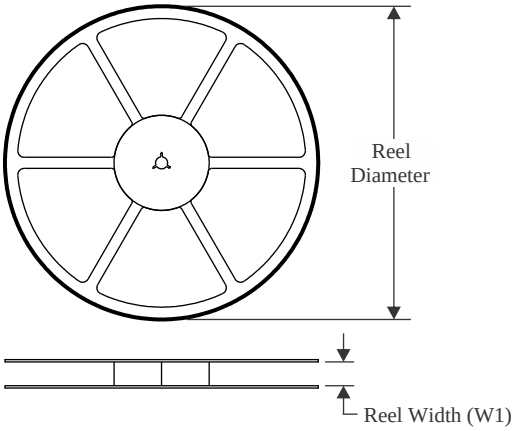
- Automotive : ISO6760-Q1, ISO6761-Q1, ISO6762-Q1, ISO6763-Q1

NOTE: Qualified Version Definitions:

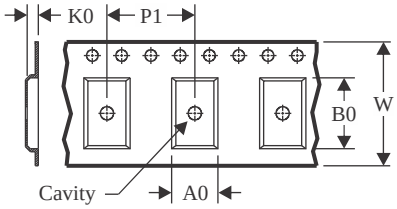
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

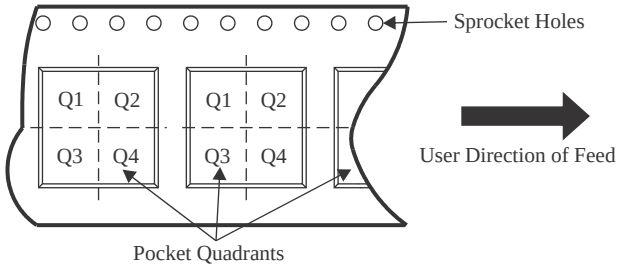


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

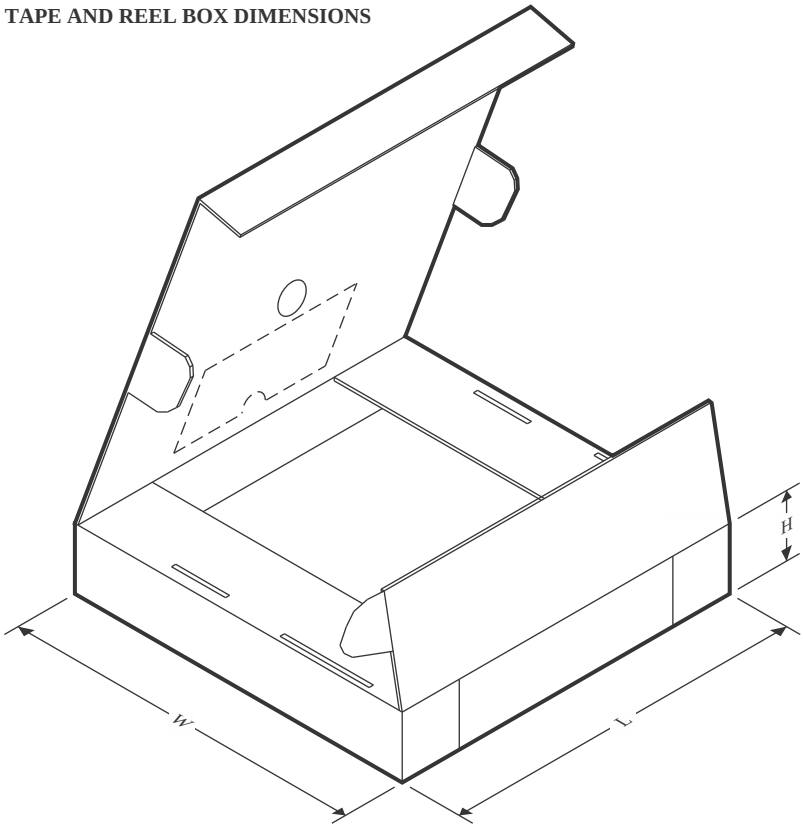


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ISO6760DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6760FDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6760FDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6761DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6761DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6761DWRG4	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6761DWRG4	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6761FDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6761FDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6761FDWRG4	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6761FDWRG4	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6762DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6762DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6762FDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6763DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6763DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ISO6763FDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO6763FDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ISO6760DWR	SOIC	DW	16	2000	353.0	353.0	32.0
ISO6760FDWR	SOIC	DW	16	2000	356.0	356.0	45.0
ISO6760FDWR	SOIC	DW	16	2000	353.0	353.0	32.0
ISO6761DWR	SOIC	DW	16	2000	356.0	356.0	45.0
ISO6761DWR	SOIC	DW	16	2000	353.0	353.0	32.0
ISO6761DWRG4	SOIC	DW	16	2000	353.0	353.0	32.0
ISO6761DWRG4	SOIC	DW	16	2000	356.0	356.0	45.0
ISO6761FDWR	SOIC	DW	16	2000	356.0	356.0	45.0
ISO6761FDWR	SOIC	DW	16	2000	353.0	353.0	32.0
ISO6761FDWRG4	SOIC	DW	16	2000	353.0	353.0	32.0
ISO6761FDWRG4	SOIC	DW	16	2000	356.0	356.0	45.0
ISO6762DWR	SOIC	DW	16	2000	356.0	356.0	45.0
ISO6762DWR	SOIC	DW	16	2000	353.0	353.0	32.0
ISO6762FDWR	SOIC	DW	16	2000	353.0	353.0	32.0
ISO6763DWR	SOIC	DW	16	2000	353.0	353.0	32.0
ISO6763DWR	SOIC	DW	16	2000	356.0	356.0	45.0
ISO6763FDWR	SOIC	DW	16	2000	356.0	356.0	45.0
ISO6763FDWR	SOIC	DW	16	2000	353.0	353.0	32.0

GENERIC PACKAGE VIEW

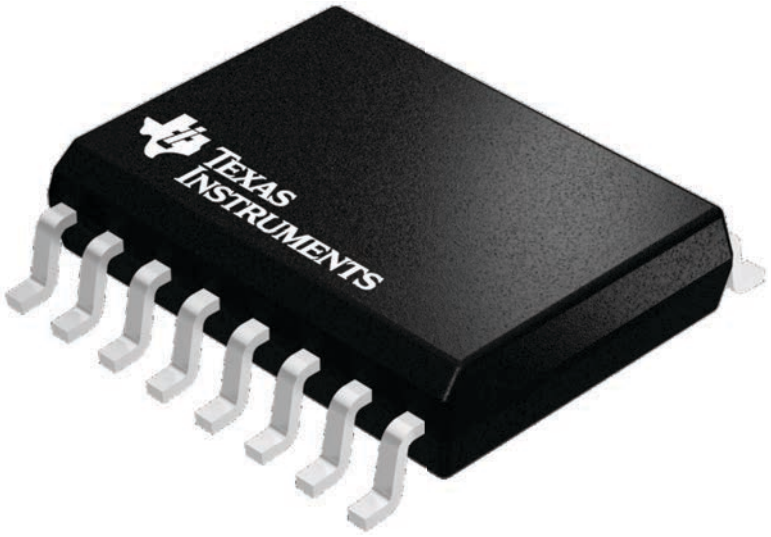
DW 16

SOIC - 2.65 mm max height

7.5 x 10.3, 1.27 mm pitch

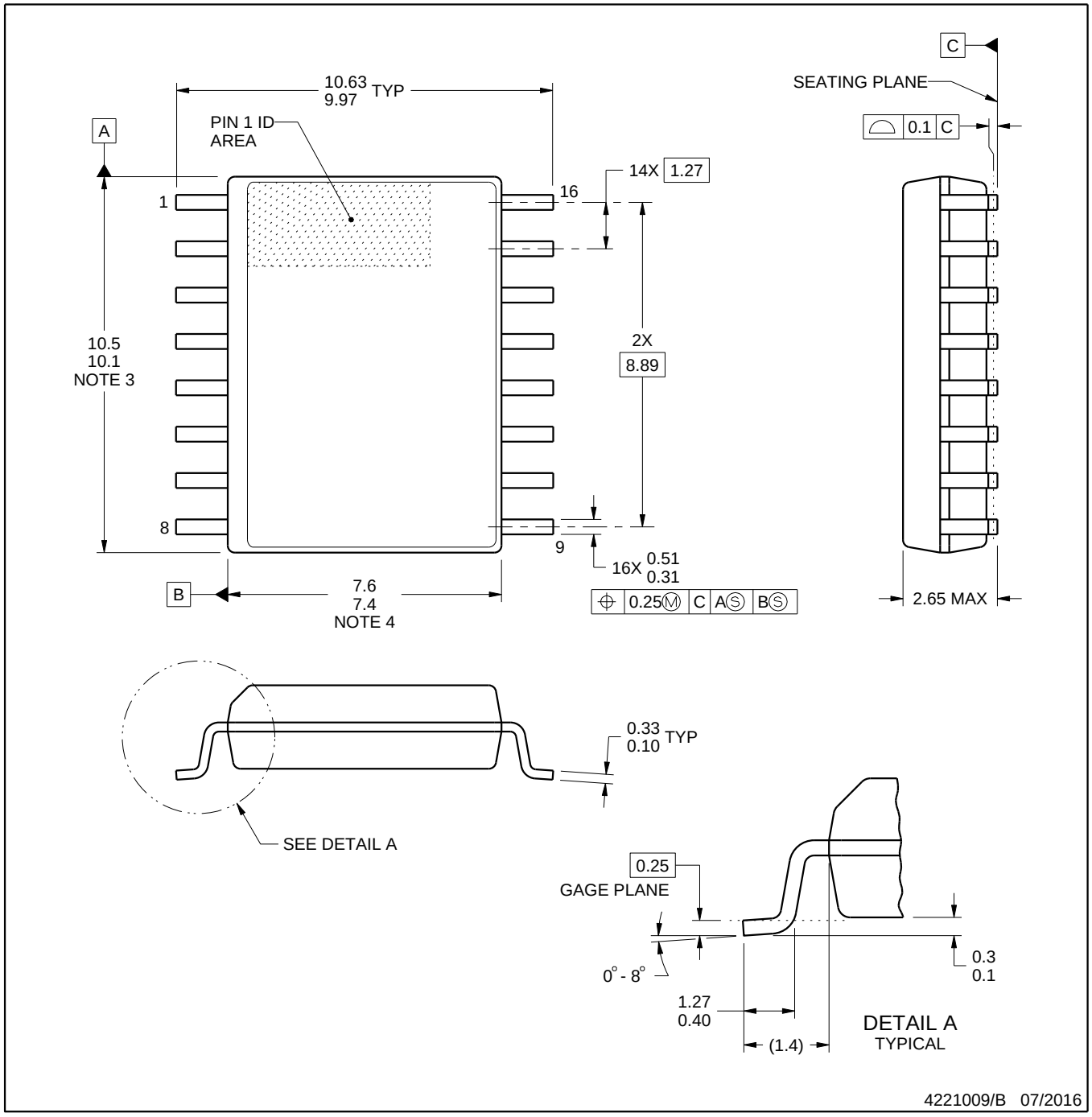
SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



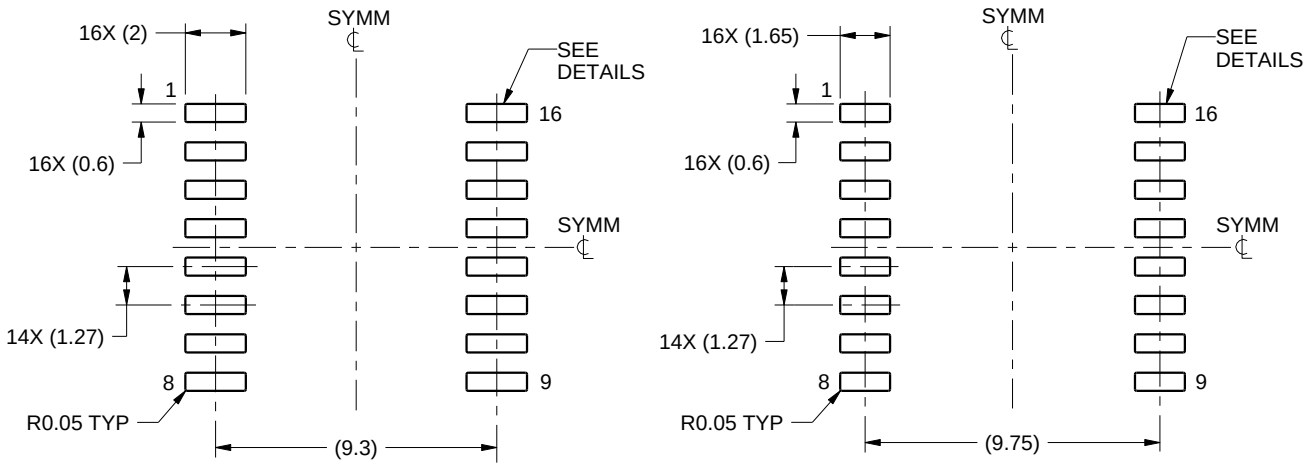
4224780/A

SOIC



NOTES:

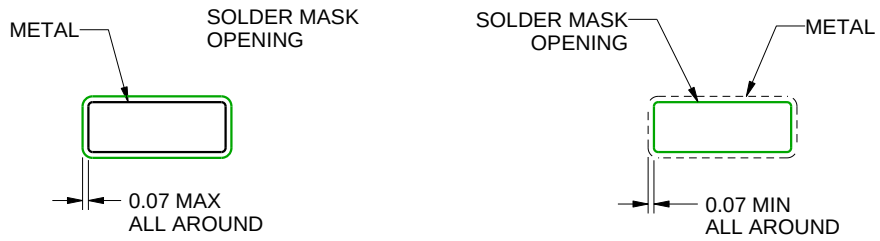
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.



IPC-7351 NOMINAL
7.3 mm CLEARANCE/CREEPAGE

HV / ISOLATION OPTION
8.1 mm CLEARANCE/CREEPAGE

LAND PATTERN EXAMPLE
SCALE:4X



NON SOLDER MASK DEFINED

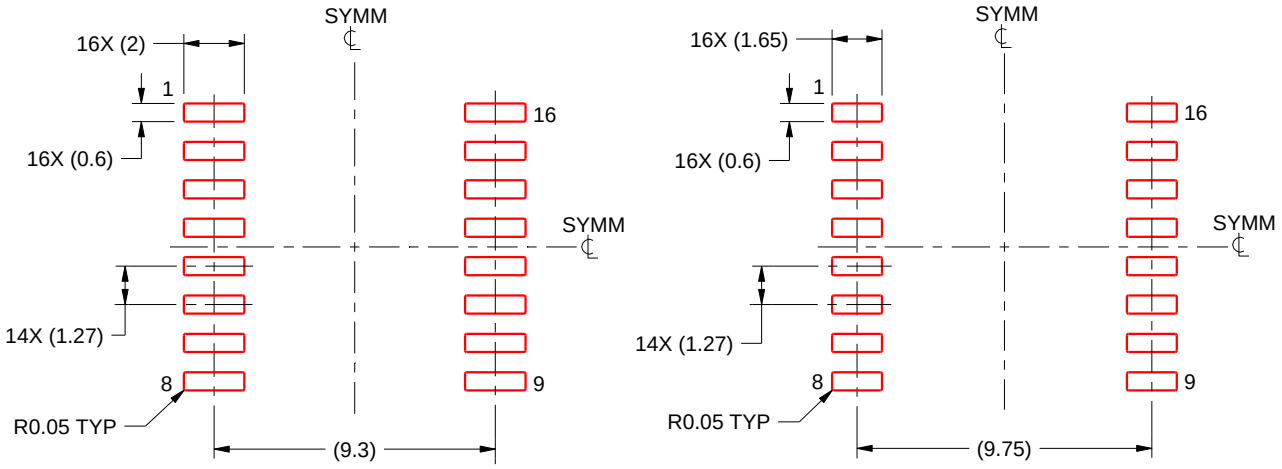
SOLDER MASK DEFINED

SOLDER MASK DETAILS

4221009/B 07/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



IPC-7351 NOMINAL
7.3 mm CLEARANCE/CREEPAGE

HV / ISOLATION OPTION
8.1 mm CLEARANCE/CREEPAGE

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:4X

4221009/B 07/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要なお知らせと免責事項

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